DAC1617D1G0

Dual 16-bit DAC, LVDS interface, up to 1 Gsps, x2, x4 and x8 interpolating

Rev. 1.1 — 30 September 2011 Objective data sheet

1. General description

The DAC1617D1G0 is a high-speed 16-bit dual channel Digital-to-Analog Converter (DAC) with selectable ×2, ×4 and ×8 interpolation filters. The device is optimized for multi-carrier and broadband wireless transmitters at sample rates of up to 1 Gsps. Supplied from a 3.3 V and a 1.8 V source, the DAC1617D1G0 integrates a differential scalable output current up to 34 mA.

The Serial Peripheral Interface (SPI) provides full control of the DAC1617D1G0.

The DAC1617D1G0 integrates a Low Voltage Differential Signaling (LVDS) Double Data Rate (DDR) receiver interface, with an on-chip 100 Ω termination. The LVDS DDR interface accepts a multiplex input data stream such as interleaved or folded. An internal LVDS input auto-calibration ensures the robustness and stability of the interface.

Digital on-chip modulation converts the complex I and Q inputs from baseband to IF. A 40-bit Numerically Controlled Oscillator (NCO) sets the mixer frequency. High resolution internal gain, phase and offset control provide outstanding image and Local Oscillator (LO) signal rejection at the system analog modulator output.

An inverse (sin x) / x function ensures a controlled flatness 0.5 dB for high bandwidths at the DAC output.

Multiple device synchronization allows synchronization of the outputs of multiple DAC devices. MDS guarantees a maximum skew of one output clock period between several devices.

The DAC1617D1G0 includes a very low noise capacitor-free integrated Phase-Locked Loop (PLL) multiplier which generates a DAC clock rate from the LVDS clock rate.

The DAC1617D1G0 is available in an HVQFN72 package (10 mm × 10 mm).

2. Features and benefits

- Dual-channel 16-bit resolution
- 1 Gsps maximum update rate
- Selectable ×2, ×4 and ×8 interpolation filters
- Very low noise capacitor-free integrated Phase-Locked Loop (PLL)
- Synchronization of multiple DAC devices
- 3-wire or 4-wire mode SPI interface
- Differential scalable output current from 8.1 mA to 34 mA
- External analog offset control (10-bit auxiliary DACs)

- Embedded Numerically Controlled Oscillator (NCO) with 40-bit programmable frequency
- Embedded complex(I/Q) digital IF modulator
- 1.8 V and 3.3 V power supplies
- LVDS DDR compatible input interface with on-chip 100 Ω terminations
- LVDS DDR input clock up to 312.5 MHz
- LVDS or LVPECL compatible DAC clock
- Interleaved or folded I and Q data input mode
- High resolution internal digital gain and offset control to support high performance IQ-modulator image rejection
- Internal phase correction
- Inverse (sin x) / x function
- Power-down mode and Sleep mode; 5-bit NCO low power mode
- On-chip 1.25 V reference
- Industrial temperature range −40 °C to +85 °C
- 72 pins small form factor HVQFN package

3. Applications

- Wireless infrastructure: LTE, WiMAX, GSM, CDMA, WCDMA, TD-SCDMA
- Communications: LMDS/MMDS, point-to-point
- Direct Digital Synthesis (DDS)
- Broadband wireless systems
- Digital radio links
- Instrumentation
- Automated Test Equipment (ATE)

4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
DAC1617D1G0HN	HVQFN72	plastic thermal enhanced very thin quad flat package; no leads; 72 terminals; body 10 × 10 × 0.85 mm	SOT813-3

5. Block diagram

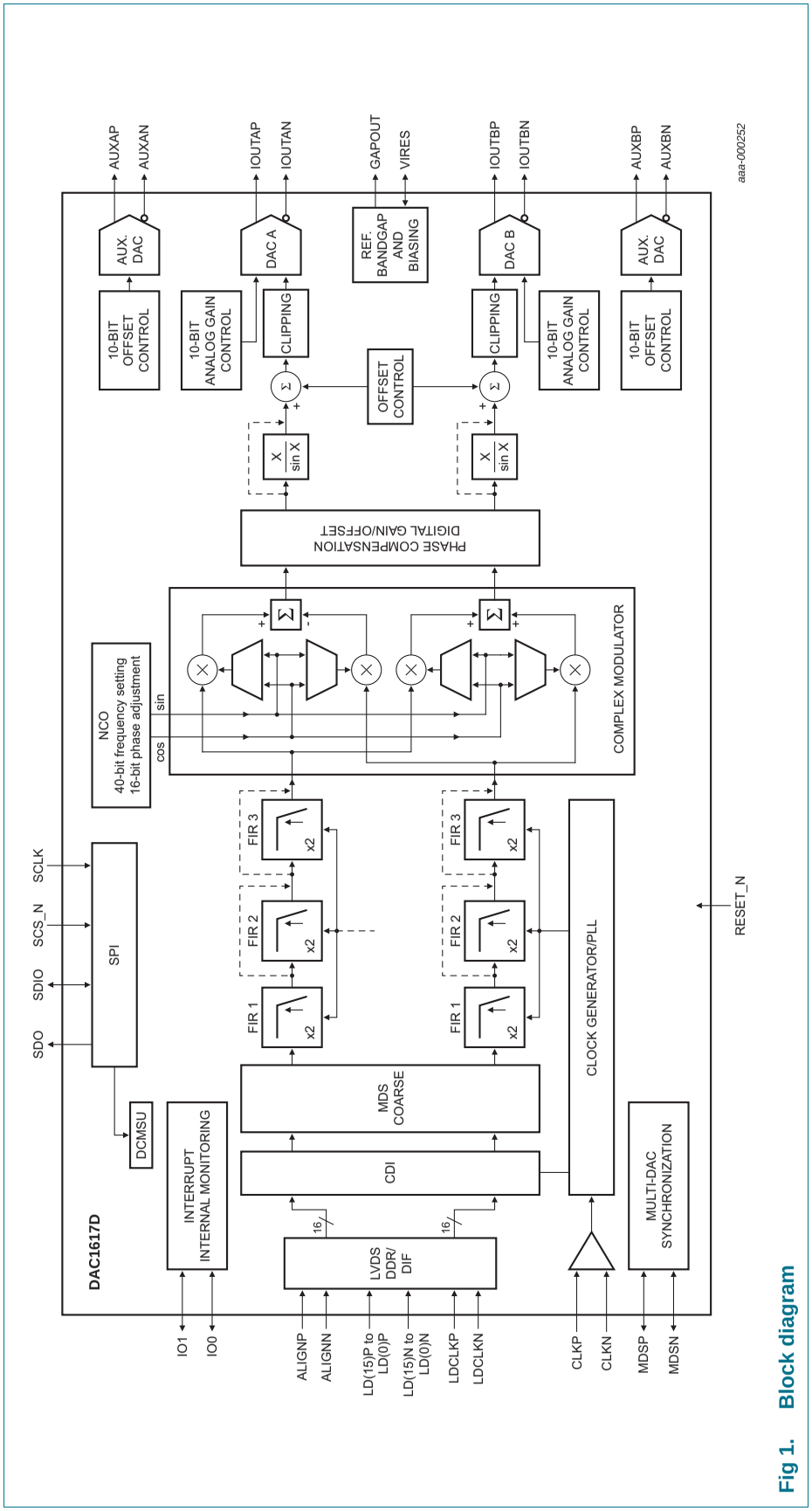


Fig 1. Block diagram

6. Pinning information

6.1 Pinning

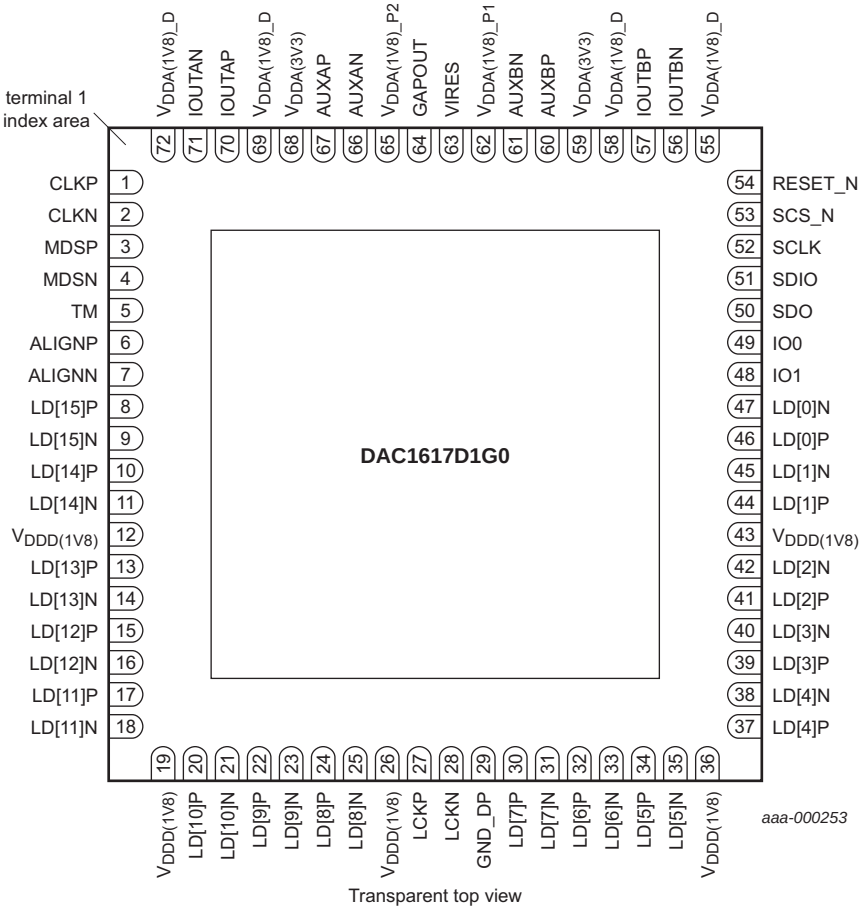


Fig 2. Pin configuration

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Type[1]	Description
CLKP	1	I	DAC clock positive input
CLKN	2	I	DAC clock negative input
MDSP	3	IO	multi-device synchronization positive signal
MDSN	4	IO	multi-device synchronization negative signal
TM	5	I	Test mode selection (connect to GND)
ALIGNP	6	I	positive input for data alignment
ALIGNN	7	I	negative input for data tanglement
LD[15]P	8	I	LVDS positive input bit 15[2]
LD[15]N	9	I	LVDS negative input bit 15[2]

Table 2. Pin description *...continued*

Symbol	Pin	Type[1]	Description
LD[14]P	10	I	LVDS positive input bit 14[2]
LD[14]N	11	I	LVDS negative input bit 14[2]
$V_{DDD(1V8)}$	12	P	1.8 V digital power supply
LD[13]P	13	I	LVDS positive input bit 13[2]
LD[13]N	14	I	LVDS negative input bit 13[2]
LD[12]P	15	I	LVDS positive input bit 12[2]
LD[12]N	16	I	LVDS negative input bit 12[2]
LD[11]P	17	I	LVDS positive input bit 11[2]
LD[11]N	18	I	LVDS negative input bit 11[2]
$V_{DDD(1V8)}$	19	P	1.8 V digital power supply
LD[10]P	20	I	LVDS positive input bit 10[2]
LD[10]N	21	I	LVDS negative input bit 10[2]
LD[9]P	22	I	LVDS positive input bit 9[2]
LD[9]N	23	I	LVDS negative input bit 9[2]
LD[8]P	24	I	LVDS positive input bit 8[2]
LD[8]N	25	I	LVDS negative input bit 8[2]
$V_{DDD(1V8)}$	26	P	1.8 V digital power supply
LCKP	27	I	LVDS positive data clock input
LCKN	28	I	LVDS negative data clock input
GND_DP	29	G	connect to ground
LD[7]P	30	I	LVDS positive input bit 7[2]
LD[7]N	31	I	LVDS negative input bit 7[2]
LD[6]P	32	I	LVDS positive input bit 6[2]
LD[6]N	33	I	LVDS negative input bit 6[2]
LD[5]P	34	I	LVDS positive input bit 5[2]
LD[5]N	35	I	LVDS negative input bit 5[2]
$V_{DDD(1V8)}$	36	P	1.8 V digital power supply
LD[4]P	37	I	LVDS positive input bit 4[2]
LD[4]N	38	I	LVDS negative input bit 4[2]
LD[3]P	39	I	LVDS positive input bit 3[2]
LD[3]N	40	I	LVDS negative input bit 3[2]
LD[2]P	41	I	LVDS positive input bit 2[2]
LD[2]N	42	I	LVDS negative input bit 2[2]
$V_{DDD(1V8)}$	43	P	1.8 V digital power supply
LD[1]P	44	I	LVDS positive input bit 1[2]
LD[1]N	45	I	LVDS negative input bit 1[2]
LD[0]P	46	I	LVDS positive input bit 0[2]
LD[0]N	47	I	LVDS negative input bit 0[2]
IO1	48	IO	IO port bit 1
IO0	49	IO	IO port bit 0
SDO	50	O	SPI data output

Table 2. Pin description *...continued*

Symbol	Pin	Type[1]	Description
SDIO	51	IO	SPI data input/output
SCLK	52	I	SPI clock
SCS_N	53	I	SPI chip select (active LOW)
RESET_N	54	I	general reset (active LOW)
$V_{DDA(1V8)\_D}$	55	P	1.8 V analog power supply (DAC core)
IOUTBN	56	O	complementary DAC B output current
IOUTBP	57	O	DAC B output current
$V_{DDA(1V8)\_D}$	58	P	1.8 V analog power supply (DAC core)
$V_{DDA(3V3)}$	59	P	3.3 V analog power supply
AUXBP	60	O	auxiliary DAC B output current
AUXBN	61	O	complementary auxiliary DAC B output current
$V_{DDA(1V8)\_P1}$	62	P	1.8 V analog power supply (PLL)
VIRES	63	IO	DAC biasing resistor
GAPOUT	64	IO	band gap input/output voltage
$V_{DDA(1V8)\_P2}$	65	P	1.8 V analog power supply (PLL)
AUXAN	66	O	complementary auxiliary DAC A output current
AUXAP	67	O	auxiliary DAC A output current
$V_{DDA(3V3)}$	68	P	3.3 V analog power supply
V_{DDA1V8_D}	69	P	1.8 V analog power supply (DAC core)
IOUTAP	70	O	DAC A output current
IOUTAN	71	O	complementary DAC A output current
$V_{DDA(1V8)\_D}$	72	P	1.8 V analog power supply (DAC core)
GND	H	G	ground (exposed die pad)

[1] P: power supply; G: ground; I: input; O: output.

[2] The LVDS input data bus order can be reversed and each element can be swapped between P and N using dedicated registers (see Table 57).

7. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DDA(3V3)}$	analog supply voltage (3.3 V)			–0.5	+4.6	V
$V_{DDD(1V8)}$	digital supply voltage (1.8 V)			–0.5	+2.5	V
$V_{DDA(1V8)}$	analog supply voltage (1.8 V)		[1]	–0.5	+2.5	V
V_I	input voltage	input pins referenced to GND		–0.5	+2.5	V
V_O	output voltage	pins IOUTAP, IOUTAN, IOUTBP, IOUTBN, AUXAP, AUXAN, AUXBP and AUXBN referenced to GND		–0.5	+4.6	V
T_{stg}	storage temperature			–55	+150	°C
T_{amb}	ambient temperature			–40	+85	°C
T_j	junction temperature			–40	+125	°C

[1] Connect the analog 1.8 V power supply to pins VDDA1V8_D, VDDA1V8_P1, and VDDA1V8_P2.

8. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions		Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1]	16.2	K/W
$R_{th(j-c)}$	thermal resistance from junction to case		[1]	6.7	K/W

[1] Value for six layers board in still air with a minimum of 49 thermal vias.

9. Characteristics

Table 5. Characteristics

$V_{DDA(1V8)}$ = 1.8 V; $V_{DDD(1V8)}$ = 1.8 V; $V_{DDA(3V3)}$ = 3.3 V; Typical values measured at T_{amb} = +25 °C; R_L = 50 Ω; $I_{O(fs)}$ = 20 mA; maximum sample rate used; external PLL; no auxiliary DAC; no inverse sinus x/x; no output correction; output load condition defined in Figure 22; output level = 1 V (p-p).

Symbol	Parameter	Conditions	Test [1]	Min	Typ	Max	Unit
$V_{DDA(3V3)}$	analog supply voltage (3.3 V)		C	3.15	3.3	3.45	V
$V_{DDD(1V8)}$	digital supply voltage (1.8 V)		C	1.7	1.8	1.9	V
$V_{DDA(1V8)}$	analog supply voltage (1.8 V)		C [2]	1.7	1.8	1.9	V
$I_{DDA(3V3)}$	analog supply current (3.3 V)	Auxiliary DAC on	C	59	62	66	mA
$I_{DDD(1V8)}$	digital supply current (1.8 V)	f_s = 983.04 67; ×4 interpolation; no NCO; MDS on	C	465	520	580	mA
		f_s = 620 Msps; ×2 interpolation; NCO on; no MDS	C	385	435	485	mA
$I_{DDA(1V8)}$	analog supply current (1.8 V)	f_s = 983.04 Msps; 1 V (p-p)	C [2]	200	226	240	mA
		f_s = 620 Msps; 1 V (p-p)	C	205	226	250	mA
P_{tot}	total power dissipation	f_s = 983.04 Msps; ×4 interpolation; NCO off; MDS off	C	-	<tbd>	-	mW
		f_s = 983.04 Msps; ×4 interpolation; 5-bit NCO; MDS off	C	-	1690	-	mW
		f_s = 620 Msps; ×2 interpolation; 40-bit NCO; MDS off		-	1400	-	mW
		power-down using SPI register	C	-	66	-	mW
Clock inputs (pins CLKP, CLKN)							
$V_{i(clk)dif}$	differential clock input voltage	peak-to-peak	C	150	-	1000	mV
R_i	input resistance		D	-	200	-	kΩ
C_i	input capacitance		D	-	0.6	-	pF
Digital inputs (pins LD[15]P to LD[0]P, LD[15]N to LD[0]N, LCKP and LCKN, ALIGNP and ALIGNN)							
V_i	input voltage	$\|V_{gpd}\|$ < 50 mV [3]	C	825	-	1575	mV
V_{idth}	input differential threshold voltage	$\|V_{gpd}\|$ < 50 mV [3]	C	–100	-	+100	mV
R_i	input resistance		D	-	100	-	Ω
C_i	input capacitance		D	-	0.8	-	pF

Table 5. Characteristics *...continued*

$V_{DDA(1V8)}$ = 1.8 V; $V_{DDD(1V8)}$ = 1.8 V; $V_{DDA(3V3)}$ = 3.3 V; Typical values measured at T_{amb} = +25 °C; R_L = 50 Ω; $I_{O(fs)}$ = 20 mA; maximum sample rate used; external PLL; no auxiliary DAC; no inverse sinus x/x; no output correction; output load condition defined in Figure 22; output level = 1 V (p-p).

Symbol	Parameter	Conditions	Test [1]	Min	Typ	Max	Unit
		pins LCKP and LCKN	D	-	1.2	-	pF
Digital inputs/outputs (pins MDSN, MDSP)							
$V_{o(dif)(p-p)}$	peak-to-peak differential output voltage		C	-	500	-	mV
$C_{o(L)}$	output load capacitance	between GND and pin MDSN or MDSP	D	-	-	<tbd>	pF
C_i	input capacitance	between GND and pin MDSN or MDSP	D	-	0.6	-	pF
R_i	input resistance		D	-	100	-	Ω
V_i	input voltage	$\|V_{gpd}\|$ < 50 mV[3]	C	<tbd>	-	<tbd>	mV
V_{idth}	input differential threshold voltage	$\|V_{gpd}\|$ < 50 mV[3]	C	<tbd>	-	<tbd>	mV
Digital inputs/outputs (pins SDO, SDIO, SCLK, SCS_N, RESET_N)							
V_{IL}	LOW-level input voltage		C	GND	-	$0.3V_{DDD(1V8)}$	V
V_{IH}	HIGH-level input voltage		C	$0.7V_{DDD(1V8)}$	-	$V_{DDD(1V8)}$	V
V_{OL}	LOW-level output voltage	pins SDO and SDIO	C	GND	-	$0.1V_{DDD(1V8)}$	V
V_{OH}	HIGH-level output voltage	pins SDO and SDIO	C	$0.9V_{DDD(1V8)}$	-	$V_{DDD(1V8)}$	V
I_{IL}	LOW-level input current	maximum VIL	I	–10	-	+10	μA
I_{IH}	HIGH-level input current	maximum VIL	I	–10	-	+10	μA
C_i	input capacitance		D	-	1	-	pF
Analog outputs (pins IOUTAP, IOUTAN, IOUTBP, IOUTBN)							
$I_{O(fs)}$	full-scale output current	controlled by the analog GAIN registers (see Table 32)	D	8.1	-	34	mA
		default value	D	-	20	-	mA
V_O	output voltage	compliance range	D	2.3	-	$V_{DDA(3V3)}$	V
$V_{O(cm)}$	common-mode output voltage	1 V (p-p) DAC output	D	-	3	-	V
		2 V (p-p) DAC output		-	2.8	-	V
R_o	output resistance		D	-	250	-	kΩ
C_o	output capacitance	between pins OUTAN and OUTBN and pins OUTBN and OUTBP	D	-	5	-	pF

Table 5. Characteristics *...continued*

$V_{DDA(1V8)}$ = 1.8 V; $V_{DDD(1V8)}$ = 1.8 V; $V_{DDA(3V3)}$ = 3.3 V; Typical values measured at T_{amb} = +25 °C; R_L = 50 Ω; $I_{O(fs)}$ = 20 mA; maximum sample rate used; external PLL; no auxiliary DAC; no inverse sinus x/x; no output correction; output load condition defined in Figure 22; output level = 1 V (p-p).

Symbol	Parameter	Conditions	Test [1]	Min	Typ	Max	Unit
ΔE_O	offset error variation		D	-	<tbd>	-	ppm/°C
ΔE_G	gain error variation		D	-	<tbd>	-	ppm/°C
INL	integral non-linearity		D	-	<tbd>	-	LSB
DNL	differential non-linearity		D	-	<tbd>	-	LSB
Reference voltage output (pin GAPOUT)							
$V_{O(ref)}$	reference output voltage	T_{amb} = +25 °C	I	-	1.22	-	V
$I_{O(ref)}$	reference output current	1.25 V external voltage	D	-	40	-	μA
$\Delta V_{O(ref)}$	reference output voltage variation		C	-	<tbd>	-	ppm/°C
Analog auxiliary outputs (pins AUXAP, AUXAN, AUXBP and AUXBN)							
$I_{O(fs)}$	full-scale output current	auxiliary DAC A; differential outputs	I	-	3.1	-	mA
		auxiliary DAC B; differential outputs	I	-	3.1	-	mA
$V_{O(aux)}$	auxiliary output voltage	compliance range	C	2.3	-	$V_{DDA(3V3)}$	V
LVDS input timing							
f_{data}	data rate	input; ×2 interpolation	C	<tbd>	-	312.5	MHz
		input; ×4 interpolation	C	<tbd>	-	250	MHz
		input; ×8 interpolation	C	<tbd>	-	125	MHz
$t_{sk(clk-D)}$	skew time from clock to data input		C	–300	-	+300	ps
DAC output timing							
f_s	sampling rate		C	-	-	1000	Msps
t_s	settling time	to ± 0.5 LSB	D	-	20	-	ns
Internal PLL timing							
f_s	sampling rate		D	-	-	1000	Msps

Table 5. Characteristics *...continued*

$V_{DDA(1V8)}$ = 1.8 V; $V_{DDD(1V8)}$ = 1.8 V; $V_{DDA(3V3)}$ = 3.3 V; Typical values measured at T_{amb} = +25 °C; R_L = 50 Ω; $I_{O(fs)}$ = 20 mA; maximum sample rate used; external PLL; no auxiliary DAC; no inverse sinus x/x; no output correction; output load condition defined in Figure 22; output level = 1 V (p-p).

Symbol	Parameter	Conditions	Test [1]	Min	Typ	Max	Unit
40-bit NCO frequency range; f_s = 1000 Msps							
f_{NCO}	NCO frequency	two's complement coding					
		register value = 8000000000h	D	-	–500	-	MHz
		register value = FFFFFFFFFFh	D	-	–0.9095	-	mHz
		register value = 0000000000h	D	-	0	-	Hz
		register value = 0000000001h	D	-	+0.9095	-	mHz
		register value = 7FFFFFFFFFh	D	-	+499.99909	-	MHz
f_{step}	step frequency		D	-	0.9095	-	mHz
Low power NCO frequency range; f_s = 1000 MHz							
f_{NCO}	NCO frequency	two's complement coding					
		register value = F8000000000h	D	-	–500	-	MHz
		register value = F8000000000h	D	-	–31.25	-	MHz
		register value = 00000000000h	D	-	0	-	Hz
		register value = 08000000000h	D	-	+31.25	-	MHz
		register value = 7FFFFFFFFFh	D	-	+468.75	-	MHz
f_{step}	step frequency		D	-	31.25	-	MHz
Dynamic performance							
SFDR	spurious-free dynamic range	f_{data} = 245.76 MHz; f_s = 983.04 Msps; BW = f_s / 2					
		f_o = 20 MHz at –1 dBFS	I	-	78	-	dBc
		f_{data} = 184.32 MHz; f_s = 737.28 Msps; BW = f_s / 2					
		f_o = 20 MHz at –1 dBFS		-	78	-	dBc
$SFDR_{RBW}$	restricted bandwidth spurious-free dynamic range	f_{data} = 245.76 MHz; f_s = 983.04 Msps; f_o = 150 MHz		-		-	dBc
		BW = 100 MHz		-	78	-	dBc
		BW = 180 MHz		-	78	-	dBc

Table 5. Characteristics *...continued*

$V_{DDA(1V8)}$ = 1.8 V; $V_{DDD(1V8)}$ = 1.8 V; $V_{DDA(3V3)}$ = 3.3 V; Typical values measured at T_{amb} = +25 °C; R_L = 50 Ω; $I_{O(fs)}$ = 20 mA; maximum sample rate used; external PLL; no auxiliary DAC; no inverse sinus x/x; no output correction; output load condition defined in Figure 22; output level = 1 V (p-p).

Symbol	Parameter	Conditions	Test [1]	Min	Typ	Max	Unit
IMD3	third-order intermodulation distortion	f_{data} = 245.76 MHz; f_s = 983.04 Msps; f_{o1} = 20 MHz; f_{o2} = 21 MHz; ×4 interpolation; output level = −1 dBFS	I	-	<tbd>	-	dBc
		f_{data} = 245.76 MHz; f_s = 983.04 Msps; f_{o1} = 152 MHz; f_{o2} = 155.1 MHz; ×4 interpolation; output level = −1 dBFS	I	-	75	-	dBc
ACPR	adjacent channel power ratio	WCDMA pattern; f_s = 983.04 Msps; ×4 interpolation; f_{NCO} = 153.6 MHz					
		1 carrier; BW = 5 MHz	D	-	73	-	dBc
		2 carriers; BW = 10 MHz	D	-	70	-	dBc
		4 carriers; BW = 20 MHz	D	-	68	-	dBc
NSD	noise spectral density	f_s = 983.04 Msps; ×4 interpolation; f_o = 20 MHz at −1 dBFS	D	-	−158	-	dBm/Hz
		f_s = 983.04 Msps; ×4 interpolation; f_o = 153.6 MHz at −1 dBFS	D	-	−155	-	dBm/Hz

[1] D = guaranteed by design; C = guaranteed by characterization; I = 100 % industrially tested.

[2] Connect $V_{DDA(1V8)\_D}$, $V_{DDA(1V8)\_P1}$ and $V_{DDA(1V8)\_P2}$ to the same 1.8 V analog power supply. Use dedicated filters for the three power pins.

[3] $|V_{gpd}|$ represents the ground potential difference voltage. This voltage is the result of current flowing through the finite resistance and the inductance between the receiver and the driver circuit ground voltages.

10. Application information

10.1 General description

The DAC1617D1G0 is a dual 16-bit DAC operating up to 1000 Msps. Each DAC consists of a segmented architecture, comprising a 6-bit thermometer subDAC and a 10-bit binary weighted subDAC.

A maximum input LVDS DDR data rate of up to 312.5 MHz and a maximum output sampling rate of 1000 Msps ensure more flexibility for wide bandwidth and multi-carrier systems. The internal 40-bit NCO of the DAC1617D1G0 simplifies the frequency selection of the system. The DAC1617D1G0 provides ×2, ×4 or ×8 interpolation filters that are useful for removing the undesired images.

Each DAC generates two complementary current outputs on pins IOUTAP and IOUTAN and pins IOUTBP and IOUTBN. These outputs provide a full-scale output current ($I_{O(fs)}$) of up to 34 mA. An internal reference is available for the reference current which is externally adjustable using pin VIRES.

High resolution internal gain, phase and offset control provide outstanding image and Local Oscillator (LO) signal rejection at the system analog modulator output.

Multiple device synchronization enables synchronization of the outputs of multiple DAC devices. MDS guarantees a maximum skew of one output clock period between several devices.

All functions can be set using an SPI interface.

10.2 Serial Peripheral Interface (SPI)

10.2.1 Protocol description

The DAC1617D1G0 serial interface is a synchronous serial communication port ensures easy interface with many industry microprocessors. It provides access to the registers that define the operating modes of the chip in both write and read mode.

This interface can be configured as a 3-wire type (pin SDIO as bidirectional pin) or 4-wire type (pins SDIO and SDO as unidirectional pins, input and output port respectively). In both configurations, SCLK acts as the serial clock and SCS_N as the serial chip select.

Figure 3 shows the SPI protocol. Each read/write operation is followed by an SCS_N signal and enabled by a LOW assertion to drive the chip with 2 bytes to 5 bytes, depending on the content of the instruction byte (see Table 7).

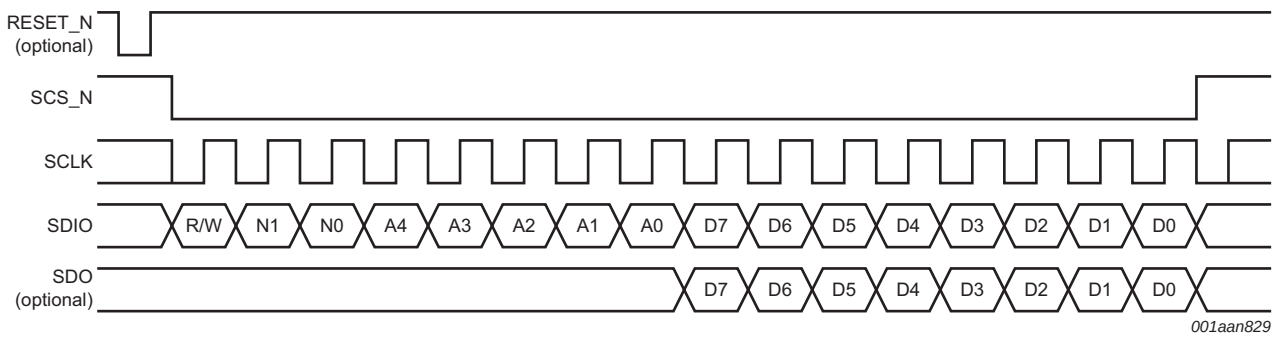


Fig 3. SPI protocol

R/W indicates the mode access (see Table 6)

Table 6. Read or Write mode access description

R/W	Description
0	Write mode operation
1	Read mode operation

Table 7 shows the number of bytes to be transferred. N1 and N0 indicate the number of bytes transferred after the instruction byte.

Table 7. Number of bytes transferred

N1	N0	Number of bytes transferred
0	0	1 byte
0	1	2 bytes
1	0	3 bytes
1	1	4 bytes

A[4:0] indicates which register is being addressed. If a multiple transfer occurs, this address concerns the first register. The other registers follow directly in a decreasing order (see Table 21, Table 35 and Table 50).

The DAC1617D1G0 incorporates more than the 32 SPI registers allowed by the address value A[4:0]. It uses three SPI register pages (page_00, page_01, and page_0A), each containing 32 registers. The 32nd register of each page indicates which page is currently addressed (00h, 01h or 0Ah).

10.2.2 SPI timing description

The SPI interface can operate at a frequency up to 15 MHz. The SPI timings are shown in Figure 4.

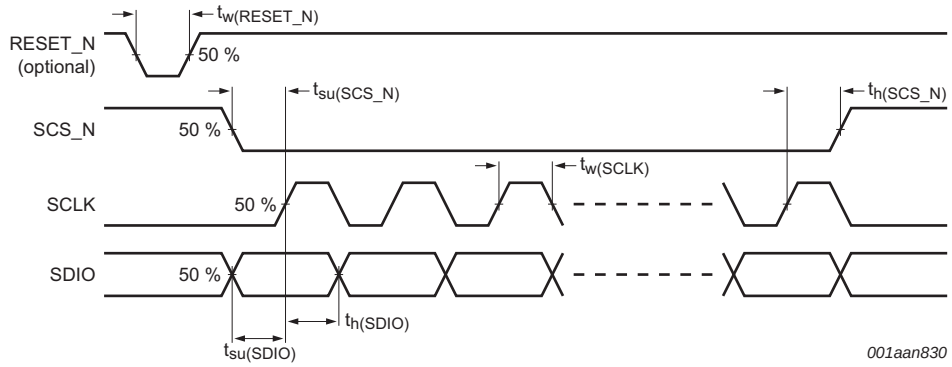


Fig 4. SPI timing diagram

The SPI timing characteristics are given in Table 8.

Table 8. SPI timing characteristics

Symbol	Parameter	Min	Typ	Max	Unit
f_{SCLK}	SCLK frequency	-	-	25	MHz
$t_{w(SCLK)}$	SCLK pulse width	30	-	-	ns
$t_{su(SCS\_N)}$	SCS_N set-up time	20	-	-	ns
$t_{h(SCS\_N)}$	SCS_N hold time	20	-	-	ns
$t_{su(SDIO)}$	SDIO set-up time	10	-	-	ns
$t_{h(SDIO)}$	SDIO hold time	5	-	-	ns
$t_{w(RESET\_N)}$	RESET_N pulse width	30	-	-	ns

10.3 Power-on sequence

There are three steps for the power-on sequence (see Figure 5):

1. The board is power-on. At the turn-on time, all DAC1617D1G0 supplies have reached their specification ranges.
2. At least 1 μs after the turn-on time pin RESET_N must be released.
3. When the DAC clock and LVDS clock are stable, the SPI configuration is sent to the DAC1617D1G0. Writing 0 in bits RST_DCLK and RST_LCLK of the register MAIN_CNTRL (see Table 51) starts the automatic calibration. 30 μs after this calibration, the DAC1617D1G0 is operational.

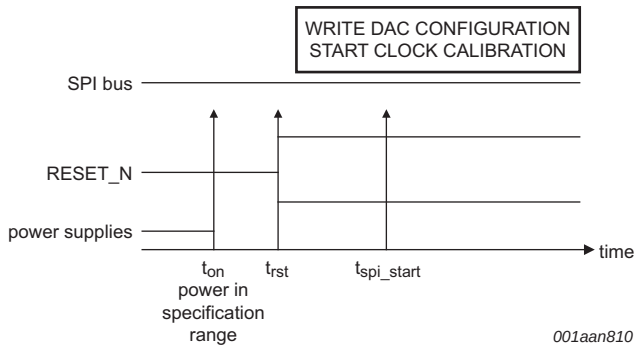


Fig 5. Power-on sequence

10.4 LVDS Data Input Format (DIF) block

The Data Input Formatting (DIF) block captures and resynchronizes data on the LVDS bus with its own LCLKP/LCLKN clock. Each LVDS input buffer has an internal resistance of 100 Ω, so an external resistor is not required. The DIF block includes two subblocks:

- **LDVS receiver:**

  Provides high flexibility for the LVDS interface, especially for the PCB layout and the control of the input port polarity and the input port mapping.

- **Data format block:**

  Enables the adaptation, which ensures the support of several data encoding modes.

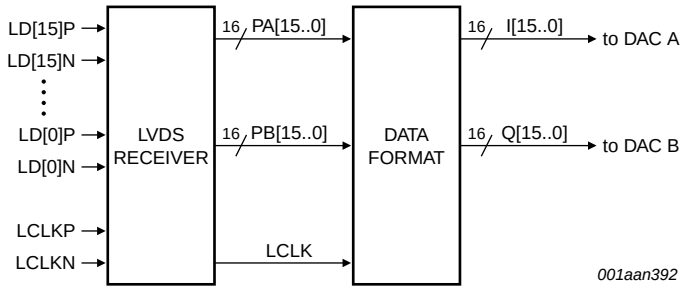


Fig 6. LVDS Data Input Format (DIF) block diagram

10.4.1 Input port polarity

The polarity of each individual LVDS input (LD[15]P to LD[0]P and LD[15]N to LD[0]N) can be changed, ensuring a much easier PCB layout design. The input polarity is controlled with bits LD_POL[15:0] (see Table 56).

10.4.2 Input port mapping

Inverting the order of the LSB and the MSB of the LVDS bus using bit WORD_SWAP in register LD_CNTRL (see Table 57) also simplifies the design of the PCB (see Table 9).

Table 9. Input LVDS bus swapping

Internal LVDS bus	External LVDS bus (WORD_SWAP = 0)	External LVDS bus (WORD_SWAP = 1)
LDI[15]P,N	LD[15]P,N	LD[0]P,N
LDI[14]P,N	LD[14]P,N	LD[1]P,N
LDI[13]P,N	LD[13]P,N	LD[2]P,N
LDI[12]P,N	LD[12]P,N	LD[3]P,N
LDI[11]P,N	LD[11]P,N	LD[4]P,N
LDI[10]P,N	LD[10]P,N	LD[5]P,N
LDI[9]P,N	LD[9]P,N	LD[6]P,N
LDI[8]P,N	LD[8]P,N	LD[7]P,N
LDI[7]P,N	LD[7]P,N	LD[8]P,N
LDI[6]P,N	LD[6]P,N	LD[9]P,N
LDI[5]P,N	LD[5]P,N	LD[10]P,N
LDI[4]P,N	LD[4]P,N	LD[11]P,N
LDI[3]P,N	LD[3]P,N	LD[12]P,N
LDI[2]P,N	LD[2]P,N	LD[13]P,N
LDI[1]P,N	LD[1]P,N	LD[14]P,N
LDI[0]P,N	LD[0]P,N	LD[15]P,N

10.4.3 Input port swapping

The LVDS DDR receiver block internally maps the incoming LVDS data bus into two buses with a single data rate (Figure 7).

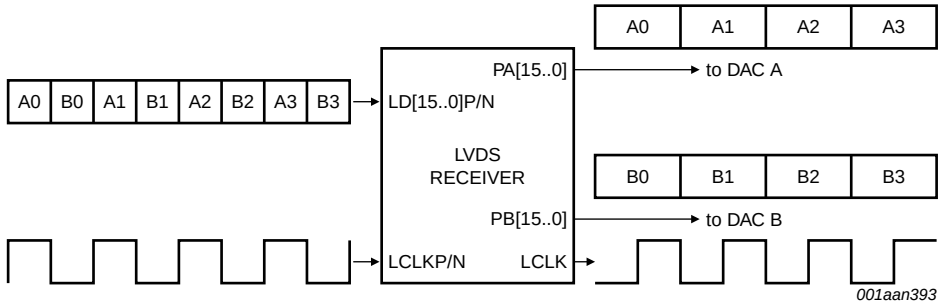


Fig 7. LVDS DDR receiver mapping LDAB SWAP = 0

These two buses can be swapped internally using bit LDAB_SWAP of register LD_CNTRL (see Table 57 and Figure 8).

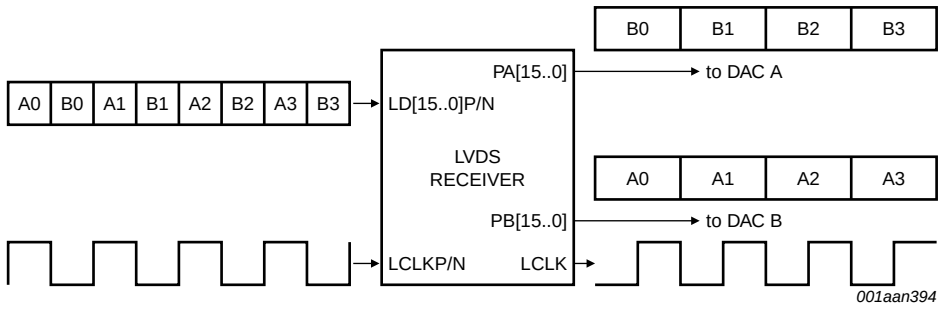


Fig 8. LVDS DDR receiver mapping LDAB SWAP = 1

10.4.4 Input port formatting

The LVDS DDR input bus multiplexes two 16-bit streams. The LVDS receiver block demultiplexes these two streams.

The two streams can carry two data formats:

- Folded
- Interleaved

The data format block is in charge of the data format adaptation (see Figure 9).

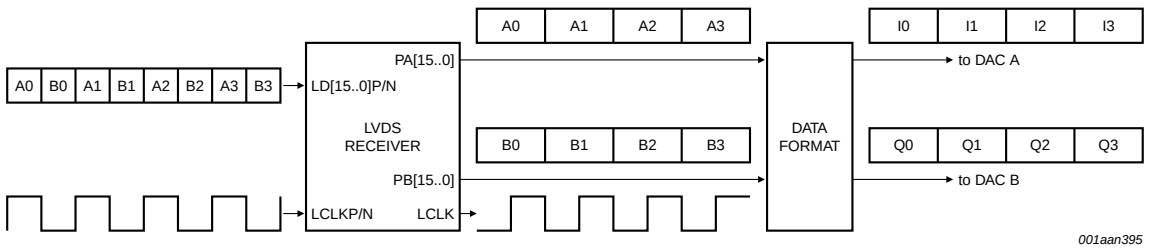


Fig 9. LVDS DDR data formats

The DAC1617D1G0 can correctly decode the input stream using bit IQ_FORMAT of register LD_CNTRL (see Table 57), because it can determine which format is used on the LVDS DDR bus.

Table 10 shows the format mapping between the LVDS input data and the data sent to the two DAC channels depending on the data format selected.

Table 10. Folded and interleaved format mapping

Data format	Data bit mapping
interleaved format (IQ_FORMAT = 1)	In[15..0] = An[15..0]; Qn[15..0] = Bn[15..0]
folded format (IQ_FORMAT = 0)	In[15..8] = An[15..8]; In[7..0] = Bn[15..8] Qn[15..8] = An[7..0]; Qn[7..0] = Bn[7..0]

10.5 Input clock

The DAC1617D1G0 operates with two clocks, one for the LVDS DDR interface and one for the DAC core.

10.5.1 LVDS DDR clock

The LVDS DDR clock can be interfaced as shown in Figure 10 because the clock buffer contains a 100 Ω internal resistor.

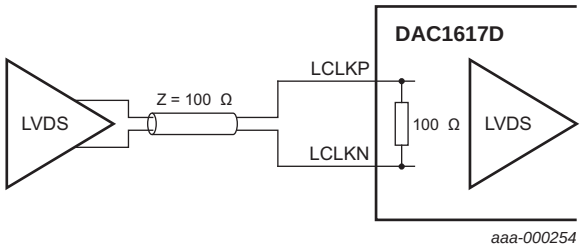
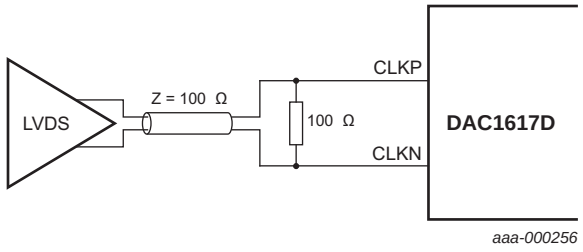


Fig 10. LVDS DDR clock configuration

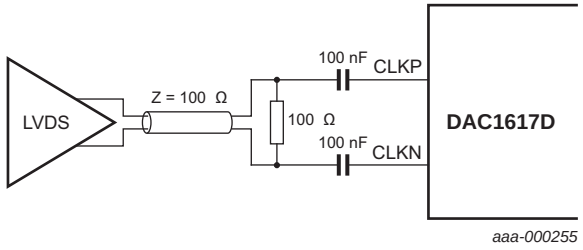
10.5.2 DAC core clock

The DAC core clock can achieve a frequency of up to 1 Gsps. It includes internal biasing to support both AC-coupling and DC-coupling. The clock can be easily connected to any LVDS, CML or PECL clock sources.

Depending on the interface selected, the hardware configuration varies (see Figure 11 to Figure 13).



a. DC-coupling



b. AC-coupling

Fig 11. DAC core clock: LVDS configuration

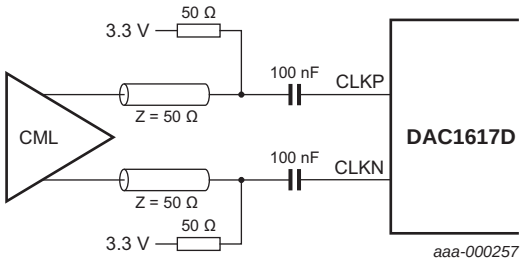


Fig 12. DAC core clock: CML configuration with AC-coupling

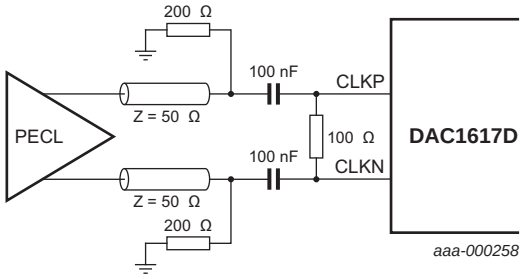


Fig 13. DAC core clock: PECL configuration with AC-coupling

10.6 Timing

The DAC1617D1G0 can operate at an update rate (f_s) of up to 1 Gsps and with an input data rate (f_{data}) of up to 312.5 MHz.

The sampling position of the LVDS data can be tuned using a 16-step compensation delay clock. The delay clock (see Figure 14, signals LDCLKPcp and LDCLKNcp) is used internally to obtain a control signal. This enables calibrating the compensation delay at start-up and monitoring if the sampling position is properly aligned.

Figure 14 shows how the compensation delay helps to recover the LVDS DDR data on both the A and B paths.

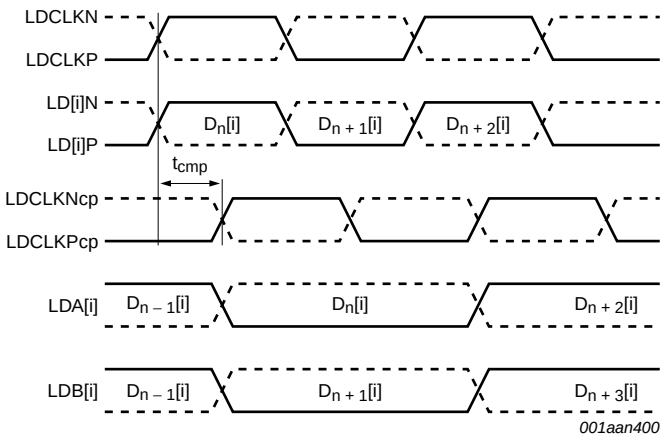
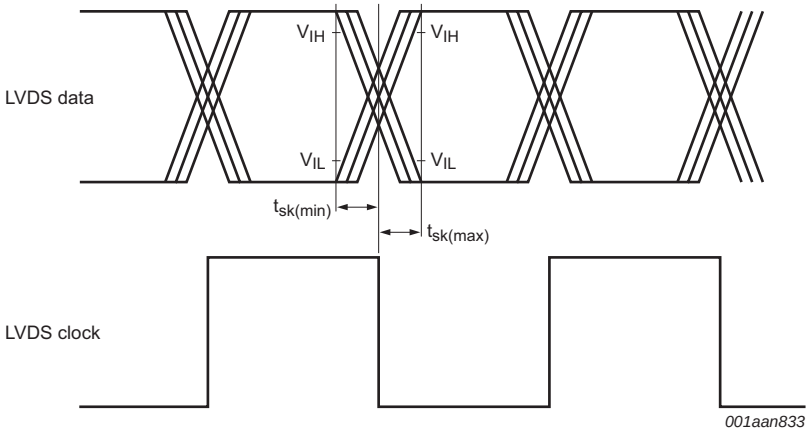


Fig 14. LVDS DDR demux timing (LVDS A and B paths not swapped; LDAB_SWAP = 0)

The compensation delay time, referred to as t_{cmp} in Figure 14, can be tuned automatically or manually.

Automatic tuning is recommended for a high-speed LVDS data rate (> 300 MHz). The external LVDS data and clock signals aligns the rising and falling edges. The timing requirement is defined in Figure 15 and in Table 5.



$t_{sk(min)}$ = minimum skew time

$t_{sk(max)}$ = maximum skew time

Fig 15. Timing requirement automatic tuning

When tuning manually, the compensation delay time (t_{cmp} in Figure 14), can be tuned as shown in Table 11 using bits LDCLK_DEL[3:0] of register MAN_LDCLKDEL (see Table 52) and bit CAL_CNTRL of register MAIN_CNTRL (see Table 51).

Table 11. Compensation delay values for manual tuning

LDCLK_DEL[3:0]	CAL_CNTRL	Typical compensation delay time
xxx	0	t_{cmp} controlled by DCSMU block (automatic control)
0000	1	360 ps to 405 ps
0001	1	435 ps to 540 ps
0010	1	525 ps to 645 ps
0011	1	600 ps to 720 ps
0100	1	690 ps to 825 ps
0101	1	780 ps to 900 ps
0110	1	885 ps to 1035 ps
0111	1	960 ps to 1200 ps
1000	1	1260 ps to 1980 ps
1001	1	1350 ps to 2160 ps
1010	1	1440 ps to 2340 ps
1011	1	1512 ps to 2556 ps
1100	1	1566 ps to 2754 ps
1101	1	1620 ps to 2952 ps
1110	1	1674 ps to 3060 ps
1111	1	1710 ps to 3186 ps

10.7 Operating modes

The DAC1617D1G0 requires two differential clocks:

- The LVDS clock (LDCLKP, LDCLKN) for the LVDS DDR interface
- The data clock (CLKP, CLKN) for the internal PLL and the dual DAC core

Set the Clock Domain Interface (CDI) and the PLL correctly to configure the DAC1617D1G0 for an application mode. The default application is a ×2 upsampling mode (see Section 10.7.1). The CDI can also support ×4 and ×8 upsampling modes (see Section 10.7.2 and Section 10.7.3).

10.7.1 CDI mode 0 (x2 interpolation)

CDI mode 0 (×2 interpolation) is required when the value of the LVDS DDR clock is twice the internal maximum CDI frequency. Table 12 shows examples of applications using an internal PLL or an external clock for the DAC core.

Table 12. CDI mode 0: operating modes examples

LVDS DDR rate (MHz)	I rate; Q rate (Msps)	CDI mode[1]	FIR mode[2]	SSBM rate[3] (Msps)	DAC rate (Msps)	PLL configuration		
						DAC input clock[4] (MHz)	PLL status[5]	PLL divider[6]
320	320	0	×2	640	640	320	enabled	2
320	320	0	×2	640	640	640	disabled	n.a.

[1] Bits CDI_MODE[1:0] of register MISC_CNTRL (see Table 58).

[2] Bits INTERPOLATION[1:0] of register TXCFG (see Table 23).

[3] If a Single Sideband Modulator (SSBM) is used, see bits NCO_ON and MODULATION[2:0] of register TXCFG (see Table 23).

[4] Pins CLKP and CLKN (see Figure 2).

[5] Bit PLL_PD of register PLLCFG (see Table 24).

[6] Bits PLL_DIV[1:0] of register PLLCFG (see Table 24).

10.7.2 CDI mode 1 (x4 interpolation)

CDI mode 1 (×4 interpolation) is required when the values of the LVDS DDR clock and the internal CDI frequency are equal. Table 13 shows examples of applications using an internal PLL or an external clock for the DAC core.

Table 13. CDI mode 1: operating modes examples

LVDS DDR rate (MHz)	I rate; Q rate (Msps)	CDI mode[1]	FIR mode[2]	SSBM rate[3] (Msps)	DAC rate (Msps)	PLL configuration		
						DAC input clock[4] (MHz)	PLL status[5]	PLL divider[6]
250	250	1	×4	1000	1000	250	enabled	4
250	250	1	×4	1000	1000	1000	disabled	n.a.

[1] Bits CDI_MODE[1:0] of register MISC_CNTRL (see Table 58).

[2] Bits INTERPOLATION[1:0] of register TXCFG (see Table 23).

[3] If SSBM is used, see bits NCO_ON and MODULATION[2:0] of register TXCFG (see Table 23).

[4] Pins CLKP and CLKN (see Figure 2).

[5] Bit PLL_PD of register PLLCFG (see Table 24).

[6] Bits PLL_DIV[1:0] of register PLLCFG (see Table 24).

10.7.3 CDI mode 2 (x8 interpolation)

CDI mode 2 (×8 interpolation) is required when the LVDS DDR clock is half the maximum CDI frequency or less. Table 14 shows examples of applications using an internal PLL or an external clock for the DAC core.

Table 14. CDI mode 2: operating modes examples

LVDS DDR rate (MHz)	I rate; Q rate (Msps)	CDI mode[1]	FIR mode[2]	SSBM rate[3] (Msps)	DAC rate (Msps)	PLL configuration		
						DAC input clock[4] (MHz)	PLL status[5]	PLL divider[6]
125	125	2	×8	1000	1000	125	enabled	4
125	125	2	×8	1000	1000	1000	disabled	n.a.

[1] Bits CDI_MODE[1:0] of register MISC_CNTRL (see Table 58).

[2] Bits INTERPOLATION[1:0] of register TXCFG (see Table 23).

[3] If SSBM is used, see bits NCO_ON and MODULATION[2:0] of register TXCFG (see Table 23).

[4] Pins CLKP and CLKN (see Figure 2).

[5] Bit PLL_PD of register PLLCFG (see Table 24).

[6] Bits PLL_DIV[1:0] of register PLLCFG (see Table 24).

10.8 FIR filters

The DAC1617D1G0 integrates three selectable Finite Impulse Response (FIR) filters which enable the use of the device with ×2, ×4 or ×8 interpolation rates. All three interpolation FIR filters have a stop-band attenuation of at least 80 dBc and a pass-band ripple of less than 0.0005 dB. Table 15 shows the coefficients of the interpolation filters.

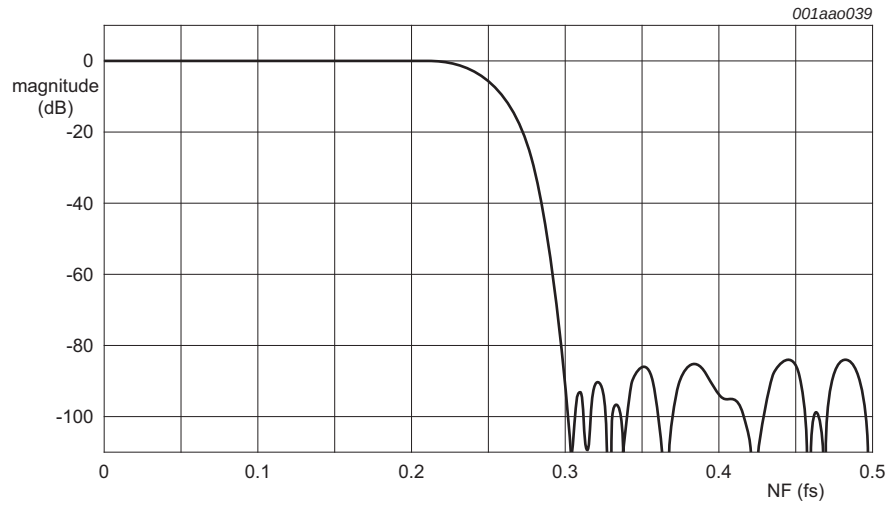


Fig 16. First stage half-band filter response

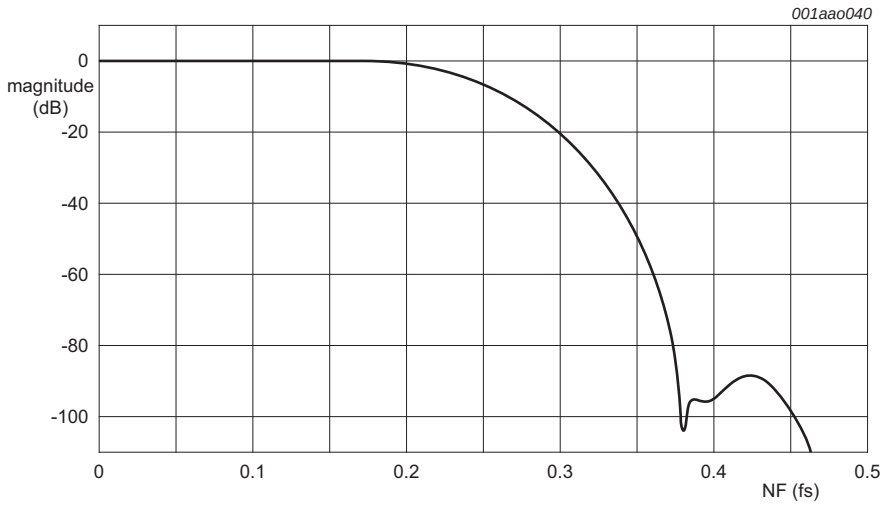


Fig 17. Second stage half-band filter response

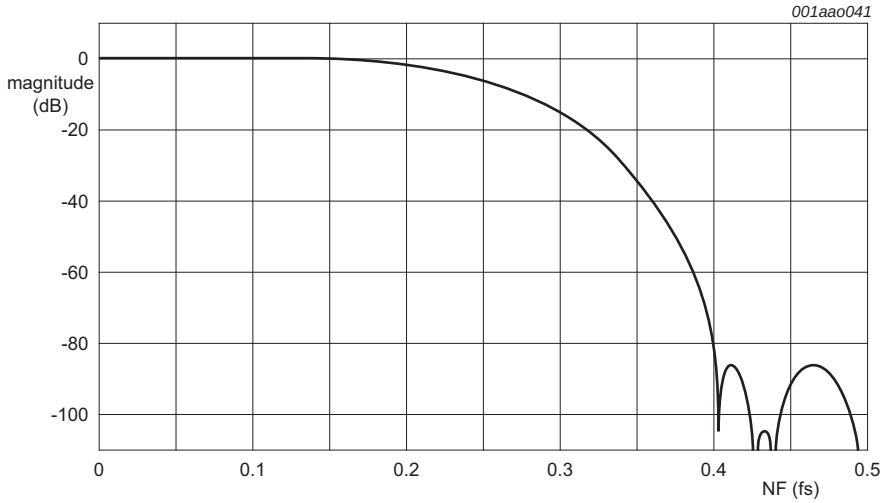


Fig 18. Third stage half-band filter response

Table 15: Interpolation filter coefficients

First interpolation filter			Second interpolation filter			Third interpolation filter		
Lower	Upper	Value	Lower	Upper	Value	Lower	Upper	Value
H(14)	-	+65536	H(6)	-	+32768	H(4)	-	+1024
H(13)	H(15)	+41501	H(5)	H(7)	+20272	H(3)	H(5)	+615
H(12)	H(16)	−13258	H(4)	H(8)	−5358	H(2)	H(6)	−127
H(11)	H(17)	+7302	H(3)	H(9)	+1986	H(1)	H(7)	+27
H(10)	H(18)	−4580	H(2)	H(10)	−654	H(0)	H(8)	−3
H(9)	H(19)	+2987	H(1)	H(11)	+159	-	-	-
H(8)	H(20)	−1951	H(0)	H(12)	−21	-	-	-
H(7)	H(21)	+1250	-	-	-	-	-	-

Table 15: Interpolation filter coefficients *...continued*

First interpolation filter			Second interpolation filter			Third interpolation filter		
Lower	Upper	Value	Lower	Upper	Value	Lower	Upper	Value
H(6)	H(22)	−773	-	-	-	-	-	-
H(5)	H(23)	+456	-	-	-	-	-	-
H(4)	H(24)	−252	-	-	-	-	-	-
H(3)	H(25)	+128	-	-	-	-	-	-
H(2)	H(26)	−58	-	-	-	-	-	-
H(1)	H(27)	+22	-	-	-	-	-	-
H(0)	H(28)	−6	-	-	-	-	-	-

10.9 Single SideBand Modulator (SSBM)

The SSBM is a quadrature modulator that enables mixing the I data and Q data with the sine and cosine signals generated by the NCO to generate path A and path B (see Figure 19).

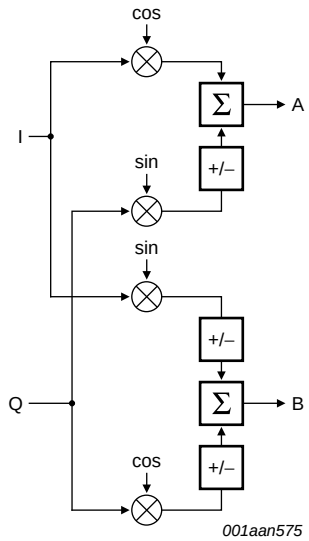


Fig 19. SSBM principle

The frequency of the NCO is programmed over 40 bits. NCO enables inverting the sine component to operate a positive or negative, lower or upper SSB upconversion (see register TXCFG in Table 23).

10.9.1 NCO in 40 bits

When using NCO, the frequency can be set over 40 bits by five registers, FREQNCO_B0 to FREQNCO_B4 (see Table 25).

The frequency is calculated with Equation 1.

$$f_{NCO} = \frac{M \times f_s}{2^{40}} \quad (1)$$

Where:

- M is the two's complement coding representation of FREQ_NCO[39:0]
- f_s is the DAC clock sampling frequency

The default settings are:

- f_{NCO} = 96 MHz
- f_s = 640 Msps

Registers PHINCO_LSB and PHINCO_MSB over 16 bits from 0° to 360° (see Table 31) can set the phase of the NCO.

10.9.2 NCO low power

The five MSB-bits of register FREQNCO_B4 (bits FREQ_NCO[39:35]; see Table 25) can set the frequency, when using NCO low power (bit NCO_LP_SEL; see Table 23).

The frequency is calculated with Equation 2.

$$f_{NCO} = \frac{M \times f_s}{2^5} \quad (2)$$

Where:

- M is the two's complement coding representation of FREQ_NCO[39:35]
- f_s is the DAC clock sampling frequency

The five MSB-bits of register PHINCO_MSB (see Table 31) can set the phase of the NCO low power.

10.9.3 Complex modulator

The complex modulator upconverts the single side band by mixing NCO signals and I and Q input signals. Table 16 shows the various possibilities set by bits MODULATION[2:0] of register TXCFG (see Table 23).

Table 16. Complex modulator operation mode

MODULATION[2:0]	Mode	Path A	Path B
000	bypass	$I(t)$	$Q(t)$
001	positive upper ssb	$I(t) \times cos(\omega_{NCO} \times t) - Q(t) \times sin(\omega_{NCO} \times t)$	$I(t) \times sin(\omega_{NCO} \times t) + Q(t) \times cos(\omega_{NCO} \times t)$
010	positive lower ssb	$I(t) \times cos(\omega_{NCO} \times t) + Q(t) \times sin(\omega_{NCO} \times t)$	$I(t) \times sin(\omega_{NCO} \times t) - Q(t) \times cos(\omega_{NCO} \times t)$
011	negative upper ssb	$I(t) \times cos(\omega_{NCO} \times t) - Q(t) \times sin(\omega_{NCO} \times t)$	$-I(t) \times sin(\omega_{NCO} \times t) - Q(t) \times cos(\omega_{NCO} \times t)$
100	negative lower ssb	$I(t) \times cos(\omega_{NCO} \times t) + Q(t) \times sin(\omega_{NCO} \times t)$	$-I(t) \times sin(\omega_{NCO} \times t) + Q(t) \times cos(\omega_{NCO} \times t)$
others	not defined	-	-

10.9.4 Minus 3dB

In normal use, a full-scale pattern is also full-scale at the DAC output. Nevertheless, when the I data and Q data come close to full-scale simultaneously, some clipping can occur. The Minus 3dB function (bit MINUS_3DB of register DAC_OUT_CTRL; see Table 28) can be used to reduce the 3 dB gain in the modulator. It retains a full-scale range at the DAC output without added interferers.

10.10 Inverse sinx / x

A selectable FIR filter is incorporated to compensate the sinx / x effect caused by the roll-off effect of the DAC. This filter has no effect at DC. It introduces a gain for high frequency. The coefficients are represented in Table 17.

Table 17. Inversion filter coefficients

First interpolation filter		
Lower	**Upper**	**Value**
H(1)	H(9)	+1
H(2)	H(8)	–4
H(3)	H(7)	+13
H(4)	H(6)	–51
H(5)	-	+610

10.11 DAC transfer function

The full-scale output current for each DAC is the sum of the two complementary current outputs:

- $I_{OA(fs)} = I_{IOUTAP} + I_{IOUTAN}$
- $I_{OB(fs))} = I_{IOUTBP} + I_{IOUTBN}$

The output current of DAC A depends on the digital input data and the gain factor defined by bits DAC_A_DGAIN[11:0] of register DAC_A_DGAIN_LSB (see Table 27).

$$I_{IOUTAP} = I_{OA(fs)} \times \frac{(DACADGAIN)}{1024} \times \left(\frac{DATA}{(65535)}\right) \quad (3)$$

$$I_{IOUTAN} = I_{OA(fs)} \times \left(1 - \frac{(DACADGAIN)}{1024} \times \left(\frac{DATA}{(65535)}\right)\right) \quad (4)$$

The output current of DAC B depends on the digital input data and the gain factor defined by bits DAC_B_DGAIN[11:0] of register DAC_B_DGAIN_LSB (see Table 27).

$$I_{IOUTBP} = I_{OB(fs)} \times \frac{(DACBDGAIN)}{1024} \times \left(\frac{DATA}{(65535)}\right) \quad (5)$$

$$I_{IOUTBN} = I_{OB(fs)} \times \left(1 - \frac{(DACBDGAIN)}{1024} \times \left(\frac{DATA}{(65535)}\right)\right) \quad (6)$$

It is possible to define if the DAC1617D1G0 operates with a binary input or a two's complement input (bit CODING; see Table 22).

Table 18 shows the output current as a function of the input data, when $I_{OA(fs)} = I_{OB(fs)} = 20$ mA.

Table 18. DAC transfer function

Data	I15 to I0/Q15 to Q0 (binary coding)	I15 to I0/Q15 to Q0 (two's complement coding	IOUTAP/IOUTBP	IOUTAN/IOUTBN
0	0000 0000 0000 0000	1000 0000 0000 0000	0 mA	20 mA
...	...	...	...	....
32768	1000 0000 0000 0000	0000 0000 0000 0000	10 mA	10 mA
...	...	...	...	...
65535	1111 1111 1111 1111	0111 1111 1111 1111	20 mA	0 mA

10.12 Full-scale current

10.12.1 Regulation

The DAC1617D1G0 reference circuitry integrates an internal band gap reference voltage which delivers a 1.25 V reference on the GAPOUT pin. Decouple pin GAPOUT using a 100 nF capacitor.

The reference current is generated via an external resistor of 910 Ω (1 %) connected to VIRES. A control amplifier sets the appropriate full-scale current ($I_{OA(fs)}$ and $I_{OB(fs)}$) for both DACs (see Figure 20)).

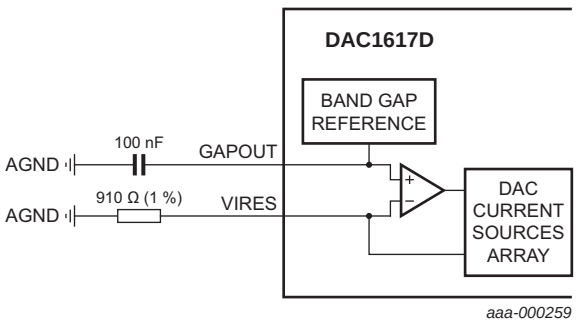


Fig 20. Internal reference configuration

Figure 20 shows the optimal configuration for temperature drift compensation because the band gap reference voltage can be matched to the voltage across the feedback resistor.

The DAC current can also be adjusted by applying an external reference voltage to the non-inverting input pin GAPOUT and by disabling the internal band gap reference voltage (bit GAP_PON of the COMMON register; see Table 22).

10.12.2 Full-scale current adjustment

The default full-scale current ($I_{O(fs)}$) is 20 mA but further adjustments can be made to both DACs independently via the serial interface from 8.1 mA to 34 mA.

The settings applied to DAC_A_GAIN[9:0] (registers 17h and 18h; see Table 32) define the full-scale current of DAC A:

$$I_{O(fs)}\ (\mu A) = 8100 + \text{DAC\_A\_GAIN[9:0]} \times 25.3 \quad (7)$$

The DAC_B_GAIN[9:0] (registers 19h and 1Ah; see Table 32;) define the full-scale current of DAC B:

$$I_{O(fs)}\ (\mu A) = 8100 + \text{DAC\_B\_GAIN[9:0]} \times 25.3 \quad (8)$$

10.13 Digital offset adjustment

The DAC1617D1G0 provides digital offset correction (bits DAC_A_OFFSET[15:0] in Table 30) which can be used to adjust the common-mode level at the output of each DAC. It adds an offset at the end of the digital part, just before the DACs. Table 19 shows the range of variation of the digital offset.

Table 19. Digital offset adjustment

DAC_A_OFFSET[15:0] DAC_B_OFFSET[15:0] (two's complement)	Offset applied
1000 0000 0000 0000	–32768
1000 0000 0000 0001	–32767
...	...
1111 1111 1111 1111	–1
0000 0000 0000 0000	0
0000 0000 0000 0001	+1
...	...
0111 1111 1111 1110	+32766
0111 1111 1111 1111	+32767

10.14 Analog output

The device has two output channels, producing two complementary current outputs, which enable the reduction of even-order harmonics and noise. The pins are IOUTAP/IOUTAN and IOUTBP/IOUTBN. Connect these pins via a load resistor R_L to the 3.3 V analog power supply ($V_{DDA(3V3)}$).

Figure 21 shows the equivalent analog output circuit of one DAC. This circuit includes a parallel combination of NMOS current sources and associated switches for each segment.

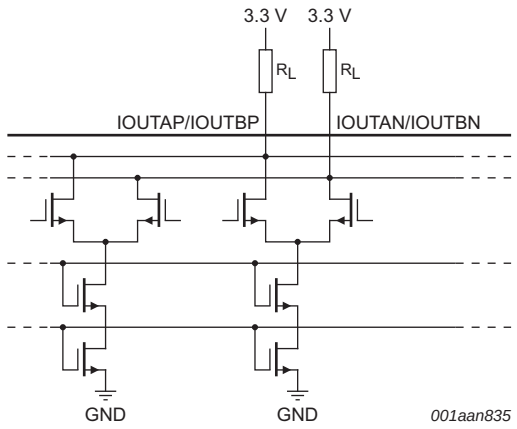


Fig 21. Equivalent analog output circuit

The cascode source configuration increases the output impedance of the source, which improves the dynamic performance of the DAC because there is less distortion.

Depending on the application, the various stages and the targeted performances, the device can be used for an output level of up to 2 V (p-p).

10.15 Auxiliary DACs

The DAC1617D1G0 integrates two auxiliary DACs, which are used to compensate any offset between the DACs and the next stage in the transmission path. Both auxiliary DACs have a 10-bit resolution and are current sources (referenced to ground).

The full-scale output current for each DAC is the sum of the two complementary current outputs:

- $I_{OAUXA(fs)} = I_{AUXAP} + I_{AUXAN}$
- $I_{OAUXB(fs)} = I_{AUXBP} + I_{AUXBN}$

The output current depends on the digital input data set by SPI registers DAC_A_Aux_MSB (bits AUX_A[9:0]) and DAC_B_Aux_MSB (bits AUX_B[9:0]; see Table 33).

$$I_{AUXAP} = I_{OAUXA(fs)} \times \left(\frac{DATAA}{1023}\right) \quad (9)$$

$$I_{AUXAN} = I_{OAUXA(fs)} \times \left(\frac{1023 - DATAA}{1023}\right) \quad (10)$$

$$I_{AUXBP} = I_{OAUXB(fs)} \times \left(\frac{DATAB}{1023}\right) \quad (11)$$

$$I_{AUXBN} = I_{OAUXB(fs)} \times \left(\frac{1023 - DATAB}{1023}\right) \quad (12)$$

Table 20 shows the output current as a function of the auxiliary DACs data DATAA and DATAB in Equation 9 to Equation 12.

Table 20. Auxiliary DAC transfer function

DATAA; DATAB	AUX_A[9:2]/AUX_A[1:0]; AUX_B[9:0]/AUX_B[1:0] (binary coding)	I_{AUXAP}; I_{AUXBP} (mA)	I_{AUXAN}; I_{AUXBN} (mA)
0	00 0000 0000	0	3.1
...	...	...	...
512	10 0000 0000	1.55	1.55
...	...	...	...
1023	11 1111 1111	3.1	0

10.16 Output configuration

10.16.1 Basic output configuration

The use of a differentially coupled transformer output (see Figure 22) provides optimum distortion performance. In addition, it helps to match the impedance and provides electrical isolation.

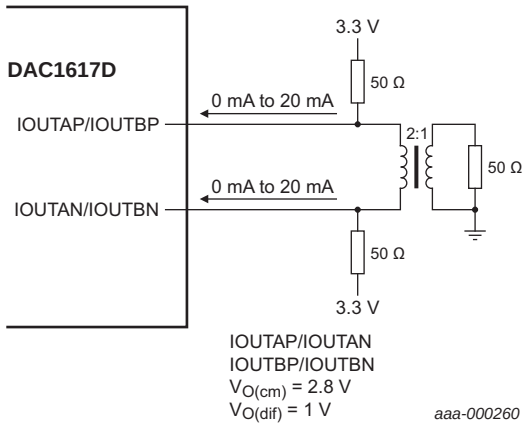


Fig 22. 1 V (p-p) differential output with transformer

The DAC1617D1G0 can operate a differential output of up to 2 V (p-p). In this configuration, connect the center tap of the transformer to a 62 Ω resistor, which is connected to the 3.3 V analog power supply. This adjusts the DC common-mode to around 2.7 V (see Figure 23).

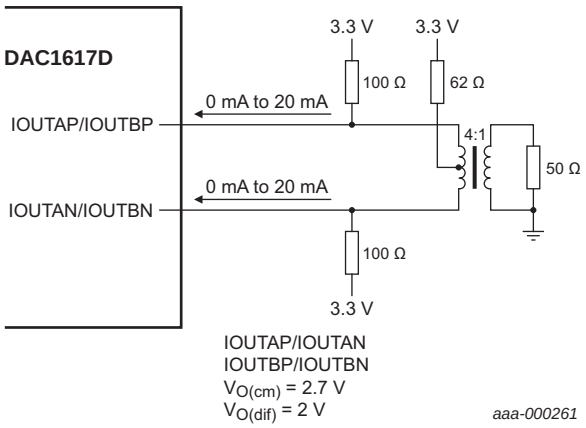


Fig 23. 2 V (p-p) differential output with transformer

10.16.2 IQ-modulator - BGX7100 interface

The DAC1617D1G0 can be easily connected to the BGX7100 NXP IQ-modulator. The offset compensation for local oscillator can be canceled using the digital offset control in the device.

Figure 24 shows an example of a connection between the DAC1617D1G0 and the BGX7100 interface.

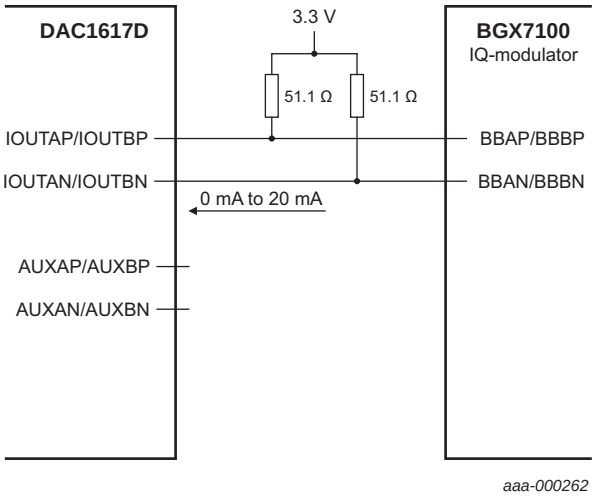


Fig 24. DAC1617D1G0 with BGX7100 IQ-modulator interface

10.16.3 IQ-modulator - DC interface

When the system operation requires to keep the DC component of the spectrum, the DAC1617D1G0 can use a DC interface to connect an IQ-modulator. In this case, the offset compensation for local oscillator can be canceled using the digital offset control in the device.

Figure 25 shows an example of a connection to an IQ modulator with a 1.7 V common input level.

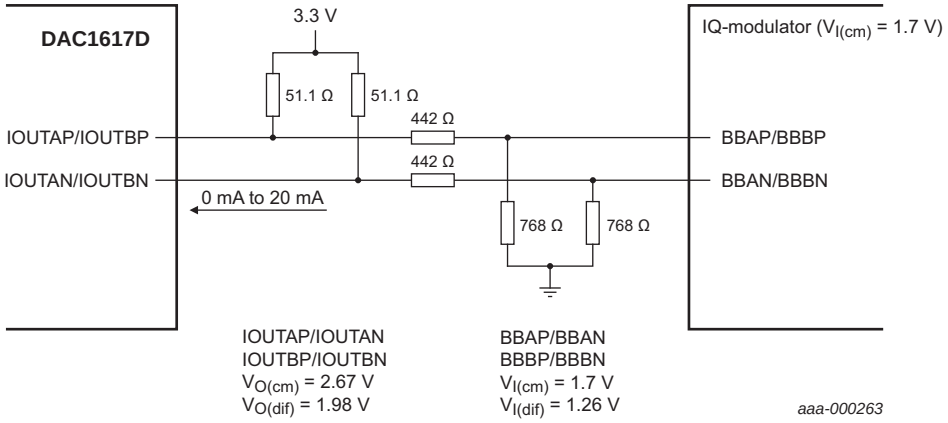


Fig 25. IQ-modulator: DC interface with a 1.7 V common input level

Figure 26 shows an example of a connection to an IQ-modulator with a 3.3 V common input level.

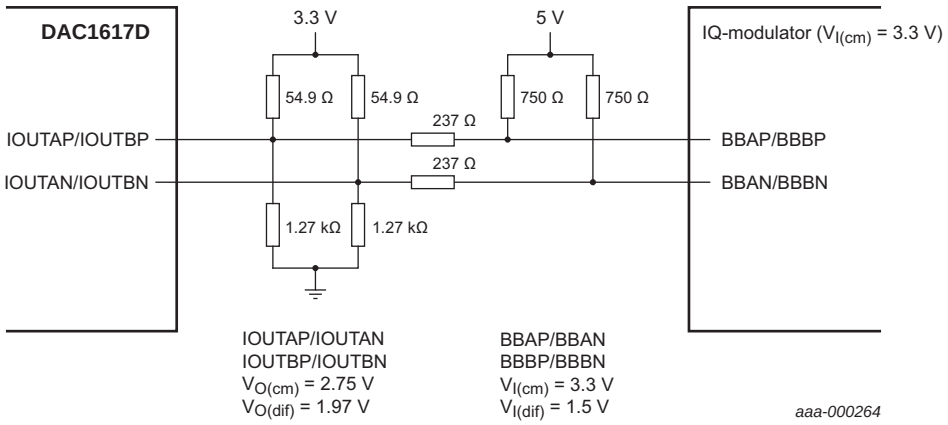


Fig 26. IQ-modulator: DC interface with a 3.3 V common input level

The auxiliary DACs can be used to control the offset within an accurate range or with accurate steps.

Figure 27 shows an example of a connection to an IQ-modulator with a 1.7 V common input level and auxiliary DACs.

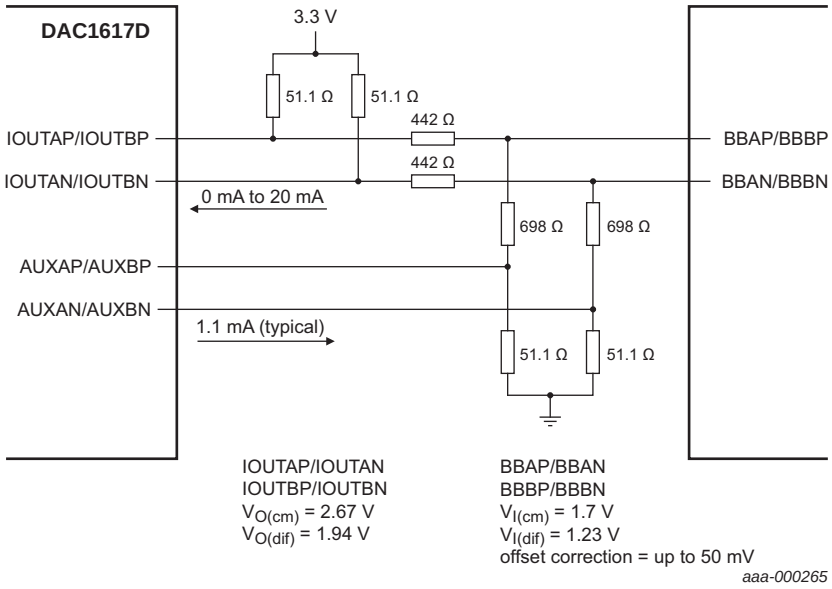


Fig 27. IQ-modulator: DC interface with a 1.7 V common input level and auxiliary DACs

Figure 28 shows an example of a connection to an IQ-modulator with a 3.3 V common input level and auxiliary DACs.

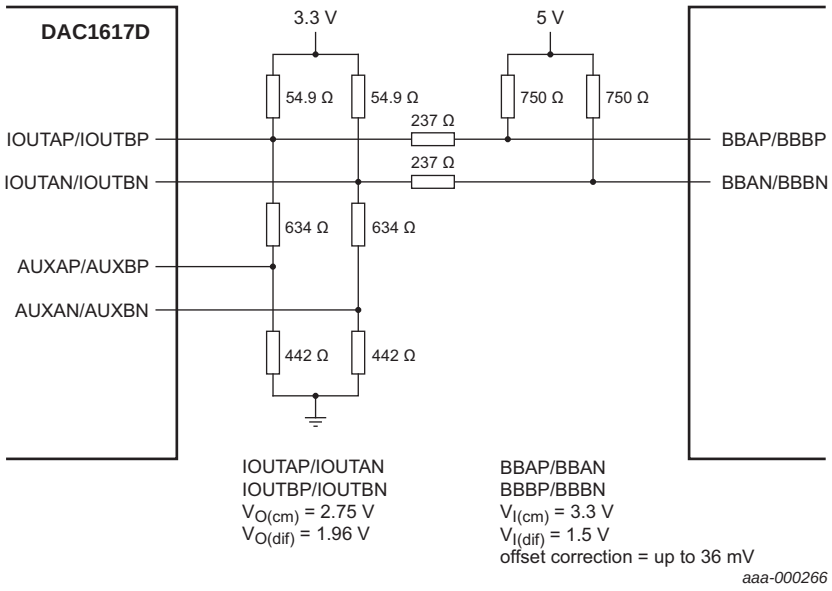


Fig 28. IQ-modulator: DC interface with a 3.3 V common input level and auxiliary DACs

The constraints to adjust the interface are:

- The output compliance range of the DAC
- The output compliance range of the auxiliary DACs
- The input common-mode level of the IQ-modulator
- The range of offset correction

10.16.4 IQ-modulator - AC interface

Use the DAC1617D1G0 AC-coupled when the IQ-modulator common-mode voltage is close to ground. The auxiliary DACs are required for local oscillator cancelation.

Figure 29 shows an example of a connection to an IQ-modulator with a 0.5 V common input level and auxiliary DACs.

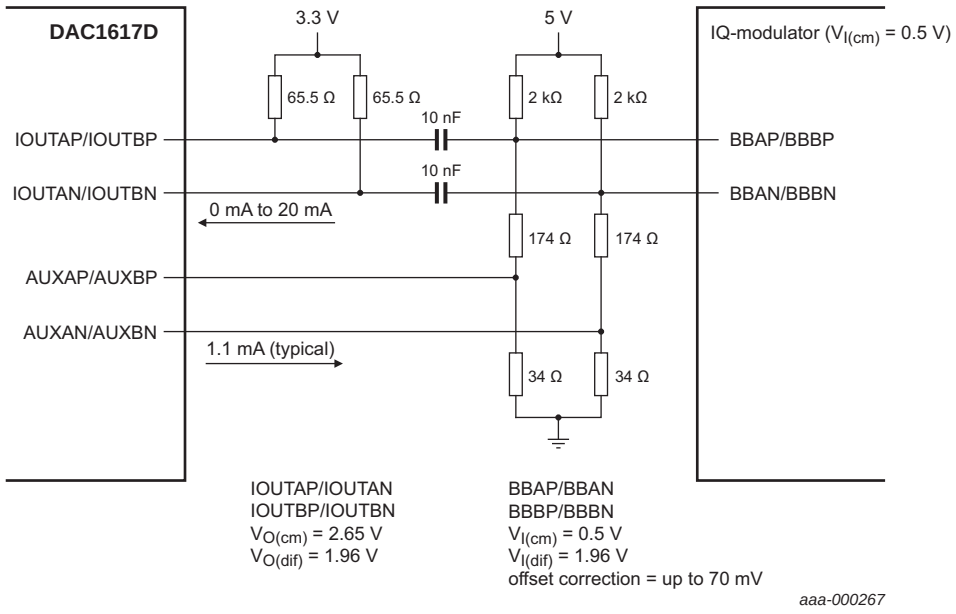


Fig 29. IQ-modulator: AC interface with a 0.5 V common input level and auxiliary DACs

10.17 Design recommendations

10.17.1 Power and grounding

Use a separate power supply regulator for the generation of the 1.8 V analog power (pins 65, 62, 55, 69, 72 and 58) and the 1.8 V digital power (pins 12, 19, 36, 26 and 43) to ensure optimal performance.

Also, include individual LC decoupling for the following six sets of power pins:

- $V_{DDA(1V8)\_P1}$ (pin 62)
- $V_{DDA(1V8)\_P2}$ (pin 65)
- $V_{DDA(1V8)}$ (pins 55, 69, 72 and 58)
- $V_{DDD(1V8)}$ (core: pins 12, 26 and 43)

- $V_{DDD(1V8)}$ (LVDS: pins 19 and 36)
- $V_{DDA(3V3)}$ (pins 59 and 68)

Use at least two capacitors for each power pin decoupling. Locate these capacitors as close as possible to the DAC1617D1G0 power pins.

The die pad is used for both the power dissipation and electrical grounding. Insert several vias (typically 7 × 7) to connect the internal ground plane to the top layer die area.

10.18 Configuration interface

10.18.1 Register description

The DAC1617D1G0 incorporates more than the 32 SPI registers allowed by the address value A[4:0]. It uses three SPI register pages (page_00, page_01, and page_0A), each containing 32 registers. The 32nd register of each page indicates which page is currently addressed (00h, 01h or 0Ah).

Page 00h (see Table 21) is dedicated to the main control of the DAC1617D1G0:

- Mode selection
- NCO control
- Auxiliary DAC control
- Gain/phase/offset control
- Power-down control

Page 01h (see Table 35) is dedicated to:

- Multi-Device Synchronization (MDS)
- DAC analog core control (biasing current, Sleep mode)

Page 0Ah (see Table 50) is dedicated to the LVDS input interface configuration.

10.18.2 Page 0 register allocation map

Table 21 shows an overview of all registers on page 0 (00h in hexadecimal).

Table 21. Page_00 register allocation map

Address		Register name	R/W	Bit definition								Default	
				Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Bin	Hex
0	00h	COMMON	R/W	3W_SPI	SPI_RST	-	-	-	CODING	IC_PON	GAP_PON	1000 0111	87h
1	01h	TXCFG	R/W	NCO_ON	NCO_LP _SEL	INV_SIN _SEL	MODULATION[2:0]			INTERPOLATION[1:0]		0000 0001	01h
2	02h	PLLCFG	R/W	PLL_BP	PLL_BUF _PD	PLL_PLL _PD	PLL_DIV[1:0]		PLL_PHASE[1:0]		PLL_ OSC_PD	1010 0001	A1h
4	04h	FREQNCO_B0	R/W	FREQ_NCO[7:0]								0110 0110	66h
5	05h	FREQNCO_B1	R/W	FREQ_NCO[15:8]								0110 0110	66h
6	06h	FREQNCO_B2	R/W	FREQ_NCO[23:16]								0110 0110	66h
7	07h	FREQNCO_B3	R/W	FREQ_NCO[31:24]								0010 0110	66h
8	08h	FREQNCO_B4	R/W	FREQ_NCO[39:32]								0010 0110	26h
9	09h	PH_CORR_CTL0	R/W	PHASE_COR[7:0]								0000 0000	00h
10	0Ah	PH_CORR_CTL1	R/W	PH_COR _ENA	-	-	PHASE_COR[12:8]					0000 0000	00h
11	0Bh	DAC_A_DGAIN_LSB	R/W	DAC_A_DGAIN[7:0]								1101 0100	50h
12	0Ch	DAC_A_DGAIN_MSB	R/W	-	-	-	-	DAC_A_DGAIN[11:8]				0000 1011	0Bh
13	0Dh	DAC_B_DGAIN_LSB	R/W	DAC_B_DGAIN[7:0]								1101 0100	50h
14	0Eh	DAC_B_DGAIN_MSB	R/W	-	-	-	-	DAC_B_DGAIN[11:8]				0000 0010	0Bh
15	0Fh	DAC_OUT_CTRL	R/W	-	-	-	-	A_DGAIN_E	B_DGAIN_E	MINUS _3DB	CLIPPING _ENA	0000 0000	00h

Table 21. Page_00 register allocation map *…continued*

Address		Register name	R/W	Bit definition								Default	
				Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Bin	Hex
16	10h	DAC_CLIPPING	R/W	CLIPPING_LEVEL[7:0]								1111 1111	FFh
17	11h	DAC_A_OFFSET_LSB	R/W	DAC_A_OFFSET[7:0]								0000 0000	00h
18	12h	DAC_A_OFFSET_MSB	R/W	DAC_A_OFFSET[15:8]								0000 0000	00h
19	13h	DAC_B_OFFSET_LSB	R/W	DAC_B_OFFSET[7:0]								0000 0000	00h
20	14h	DAC_B_OFFSET_MSB	R/W	DAC_B_OFFSET[15:8]								0000 0000	00h
21	15h	PHINCO_LSB	R/W	PH_NCO[7:0]								0000 0000	00h
22	16h	PHINCO_MSB	R/W	PH_NCO[15:8]								0000 0000	00h
23	17h	DAC_A_GAIN1	R/W	DAC_A_GAIN[7:0]								0100 0000	40h
24	18h	DAC_A_GAIN2	R/W	DAC_A_GAIN[9:8]		-	-	-	-	-	-	1000 0000	80h
25	19h	DAC_B_GAIN1	R/W	DAC_B_GAIN[7:0]								0100 0000	40h
26	1Ah	DAC_B_GAIN2	R/W	DAC_B_GAIN[9:8]		-	-	-	-	-	-	1000 0000	80h
27	1Bh	DAC_A_AUX_MSB	R/W	AUX_A[9:2]								1000 0000	80h
28	1Ch	DAC_A_AUX_LSB	R/W	AUX_A_PD	-	-	-	-	-	AUX_A[1:0]		0000 0000	00h
29	1Dh	DAC_B_AUX_MSB	R/W	AUX_B[9:2]								1000 0000	80h
30	1Eh	DAC_B_AUX_LSB	R/W	AUX_B_PD	-	-	-	-	-	AUX_B[1:0]		0000 0000	00h
31	1Fh	PAGE_ADDRESS	R/W	-	-	-	-	-	PAGE[2:0]			0000 0000	00h

10.18.3 Page 0 bit definition detailed description

The tables in this section contain detailed descriptions of the page 0 registers.

Table 22. Register COMMON (address 00h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	3W_SPI	R/W		serial interface bus type
			0	4-wire SPI
			1	**3-wire SPI**
6	SPI_RST	R/W		serial interface reset
			0	**no reset**
			1	performs a reset on all registers except address 00h
2	CODING	R/W		coding of input word
			0	two's complement coding
			1	**unsigned format**
1	IC_PON	R/W		IC power control
			0	all circuits (digital and analog, except SPI) are in power-down
			1	**all circuits (digital and analog, except SPI) are switched on**
0	GAP_PON	R/W		internal band gap power control
			0	band gap is power-down
			1	**internal band gap references are switched on**

Table 23. Register TXCFG (address 01h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	NCO_ON	R/W		NCO
			0	**NCO disabled, the NCO phase is reset to 0**
			1	NCO enabled
6	NCO_LP_SEL	R/W		NCO low power selection
			0	**low power NCO disabled**
			1	low power NCO enabled (frequency and phase given by the five MSB of the registers 06h and 08h, respectively)
5	INV_SIN_SEL	R/W		inverse (sin x) / x function selection
			0	**disable**
			1	enable
4 to 2	MODULATION[2:0]	R/W		modulation
			000	**dual DAC: no modulation**
			001	positive upper single sideband upconversion
			010	positive lower single sideband upconversion
			011	negative upper single sideband upconversion
			100	negative lower single sideband upconversion
			others	not defined

Table 23. Register TXCFG (address 01h) bit description *...continued*

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
1 to 0	INTERPOLATION[1:0]	R/W		interpolation
			00	no interpolation
			01	**×2 interpolation**
			10	×4 interpolation
			11	×8 interpolation

Table 24. Register PLLCFG (address 02h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	PLL_BP	R/W		PLL bypass
			0	DAC clock generated by PLL
			1	**DAC clock provided via external pins CLKN and CLKP (PLL bypass mode)**
6	PLL_BUF_PD	R/W		PLL test buffer control
			0	**Power-down mode**
			1	enabled
5	PLL_PLL_PD	R/W		PLL and CKGEN control
			0	Power-down mode
			1	**enable**
4 to 3	PLL_DIV[1:0]	R/W		PLL divider factor
			00	**$f_s = 2 \times f_{data}$**
			01	$f_s = 4 \times f_{data}$
			10	$f_s = 8 \times f$
			11	undefined
2 to 1	PLL_PHASE[1:0]	R/W		PLL phase shift
			00	**0 degrees phase shift of f_s**
			01	120 degrees phase shift of f_s
			10	240 degrees phase shift of f_s
			11	240 degrees phase shift of f_s
0	PLL_OSC_PD	R/W		PLL oscillator output power-down
			0	Power-down mode
			1	**enabled**

Table 25. NCO frequency registers (address 04h to 08h) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
04h	FREQNCO_B0	7 to 0	FREQ_NCO[7:0]	R/W		NCO frequency (two's complement coding)
					-	least significant 8 bits for the NCO frequency setting
05h	FREQNCO_B1	7 to 0	FREQ_NCO[15:8]	R/W	-	intermediate 8 bits for the NCO frequency setting

Table 25. NCO frequency registers (address 04h to 08h) bit description *...continued*

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
06h	FREQNCO_B2	7 to 0	FREQ_NCO[23:16]	R/W	-	intermediate 8 bits for the NCO frequency setting
07h	FREQNCO_B3	7 to 0	FREQ_NCO[31:24]	R/W	-	intermediate 8 bits for the NCO frequency setting
08h	FREQNCO_B4	7 to 0	FREQ_NCO[39:32]	R/W	-	most significant 8 bits for the NCO frequency setting

Table 26. DAC output phase correction registers (address 09h to 0Ah) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
09h	PH_CORR_CTL0	7 to 0	PHASE_COR[7:0]	R/W		DAC output phase correction factor (LSB)
					-	least significant 8 bits for the DAC output phase correction factor
0Ah	PH_CORR_CTL1	7	PH_COR_ENA	R/W		DAC output phase correction control
					0	**DAC output phase correction disabled**
					1	DAC output phase correction enabled
		4 to 0	PHASE_COR[12:8]	R/W		DAC output phase correction factor MSB
					00000	most significant 5 bits for the DAC output phase correction factor

Table 27. Digital gain control registers (address 0Bh to 0Eh) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
0Bh	DAC_A_DGAIN_LSB	7 to 0	DAC_A_DGAIN[7:0]	R/W		DAC A digital gain control
					-	least significant 8 bits for the DAC A digital gain
0Ch	DAC_A_DGAIN_MSB	3 to 0	DAC_A_DGAIN[11:8]		-	most significant 4 bits for the DAC A digital gain
0Dh	DAC_B_DGAIN_LSB	7 to 0	DAC_B_DGAIN[7:0]	R/W		DAC B digital gain control
					-	least significant 8 bits for the DAC B digital gain
0Eh	DAC_B_DGAIN_MSB	3 to 0	DAC_B_DGAIN[11:8]		-	most significant 4 bits for the DAC B digital gain

Table 28. Register DAC_OUT_CTRL (address 0Fh)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
3	A_DGAIN_E	R/W		DAC A digital gain control
			0	**disable**
			1	enable

Table 28. Register DAC_OUT_CTRL (address 0Fh) *…continued*

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
2	B_DGAIN_E	R/W		DAC B digital gain control
			0	**disable**
			1	enable
1	MINUS_3DB	R/W		DAC attenuation control
			0	**unity gain**
			1	−3 dB gain
0	CLIPPING_ENA	R/W		Digital DAC output clipping control
			0	**disable**
			1	enable

Table 29. Register DAC_CLIPPING (address 10h)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7 to 0	CLIPPING_LEVEL[7:0]	R/W	-	Digital DAC output clipping level value

Table 30. Digital offset value registers (address 11h to 14h) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
11h	DAC_A_OFFSET_LSB	7 to 0	DAC_A_OFFSET[7:0]	R/W		DAC A digital offset value
					-	least significant 8 bits for the DAC A digital offset
12h	DAC_A_OFFSET_MSB	7 to 0	DAC_A_OFFSET[15:8]		-	most significant 8 bits for the DAC A digital offset
13h	DAC_B_OFFSET_LSB	7 to 0	DAC_B_OFFSET[7:0]	R/W		DAC B digital offset value
					-	least significant 8 bits for the DAC B digital offset
14h	DAC_B_OFFSET_MSB	7 to 0	DAC_B_OFFSET[15:8]		-	most significant 8 bits for the DAC B digital offset

Table 31. NCO phase offset registers (address 15h to 16h) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
15h	PHINCO_LSB	7 to 0	PH_NCO[7:0]	R/W		NCO phase offset LSB
					-	least significant 8 bits for the NCO phase setting
16h	PHINCO_MSB	7 to 0	PH_NCO[15:8]	R/W		NCO phase offset MSB
					-	most significant 8 bits for the NCO phase setting

Table 32. Analog gain control registers (address 17h to 1Ah) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
17h	DAC_A_GAIN1	7 to 0	DAC_A_GAIN[7:0]	R/W	-	DAC A analog gain control (LSB)
18h	DAC_A_GAIN2	7 to 6	DAC_A_GAIN[9:8]	R/W	-	DAC A analog gain control (MSB)
19h	DAC_B_GAIN1	7 to 0	DAC_B_GAIN[7:0]	R/W	-	DAC B analog gain control (LSB)
1Ah	DAC_B_GAIN2	7 to 6	DAC_B_GAIN[9:8]	R/W	-	DAC B analog gain control (MSB)

Table 33. Auxiliary DAC registers (address 1Bh to 1Eh) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
1Bh	DAC_A_Aux_MSB	7 to 0	AUX_A[9:2]	R/W	-	most significant 8 bits for auxiliary DAC A
1Ch	DAC_A_Aux_LSB	7	AUX_A_PD	R/W		auxiliary DAC A power
					0	**on**
					1	off
		1 to 0	AUX_A[1:0]	R/W	-	least significant 2 bits for auxiliary DAC A
1Dh	DAC_B_Aux_MSB	7 to 0	AUX_B[9:2]	R/W	-	most significant 8 bits for auxiliary DAC B
1Eh	DAC_B_Aux_LSB	7	AUX_B_PD	R/W		auxiliary DAC B power
					0	**on**
					1	off
		1 to 0	AUX_B[1:0]	R/W	-	least significant 2 bits for auxiliary DAC B

Table 34. SPI_PAGE register (address 1Fh) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
2 to 0	PAGE[2:0]	R/W	-	SPI page address

10.18.4 Page 1 allocation map

Table 35 shows an overview of all registers on page 1 (01h in hexadecimal).

Table 35. Page 1 register allocation map

Address		Register name	R/W	Bit definition								Default[1]	
				Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Bin	Hex
0	00h	MDS_MAIN	R/W	MDS_EQCHECK[1:0]		MDS_RUN	MDS_NCO	MDS_NCO_PULSE	MDS_SREF_DIS	MDS_MASTER	MDS_ENA	0000 0100	04h
1	01h	MDS_WIN_PERIOD_A	R/W	MDS_WIN_PERIOD_A[7:0]								1000 0000	80h
2	02h	MDS_WIN_PERIOD_B	R/W	MDS_WIN_PERIOD_B[7:0]								0100 0000	40h
3	03h	MDS_MISCCNTRL0	R/W	-	-	-	MDS_EVAL_ENA	MDS_PRERUN_E	MDS_PULSEWIDTH[2:0]			0001 0000	10h
4	04h	MDS_MAN_ADJUSTDLY	R/W	MDS_MAN	MDS_MAN_ADJUSTDLY[6:0]							0100 0000	40h
5	05h	MDS_AUTO_CYCLES	R/W	MDS_AUTO_CYCLES[7:0]								1000 0000	80h
6	06h	MDS_MISCCNTRL1	R/W	MDS_SR_CKEN	MDS_SR_LOCKOUT	MDS_SR_LOCK	MDS_RELOCK	MDS_LOCK_DELAY[3:0]				0000 1111	0Fh
7	07h	MDS_OFFSET_DLY	RW	-	-	-	MDS_OFFSET_DLY[4:0]					0000 0000	00h
8	08h	MDS_ADJDELAY	RW	-	MDS_ADJDELAY[6:0]							0000 0000	00h
9	09h	MDS_STATUS0	R	EARLY	LATE	EQUAL	MDS_EQ	EARLY_ERROR	LATE_ERROR	EQUAL_FOUND	MDS_ACTIVE	uuuu uuuu	uuh
10	0Ah	MDS_STATUS1	R	-	-	ADD_ERR	MDS_EN_PHASE[1:0]		MDS_PRERUN	MDS_LOCKOUT	MDS_LOCK	uuuu uuuu	uuh
14	0Eh	DAC_CURRENT_AUX	R/W	-	-	-	-	DAC_AUX_BIAS[3:0]				0000 0011	03h
15	0Fh	DAC_CURRENT_0	R/W	-	-	-	-	DAC_DIG_BIAS[3:0]				0000 0011	03h
16	10h	DAC_CURRENT_1	R/W	-	-	-	-	DAC_MST_BIAS[3:0]				0000 0011	03h
17	11h	DAC_CURRENT_2	R/W	-	-	-	-	DAC_DRV_BIAS[3:0]				0000 0011	03h

Table 35. Page 1 register allocation map *…continued*

Address		Register name	R/W	Bit definition								Default[1]	
				Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Bin	Hex
18	12h	DAC_CURRENT_3	R/W	-	-	-	-	DAC_SLV_BIAS[3:0]				0000 0011	03h
19	13h	DAC_CURRENT_4	R/W	-	-	-	-	DAC_CK_BIAS[3:0]				0000 0011	03h
20	14h	DAC_CURRENT_5	R/W	-	-	-	-	DAC_CAS_BIAS[3:0]				0000 0011	03h
21	15h	DAC_CURRENT_6	R/W	-	-	-	-	DAC_BLD_BIAS[3:0]				0000 0011	03h
22	16h	DAC_PON_SLEEP	R/W	DAC_B_PON	DAC_B_SLEEP	DAC_B_COM_PD	DAC_B_BLEED_PD	DAC_A_PD	DAC_A_SLEEP	DAC_A_COM_PD	DAC_A_BLEED_PD	1011 1011	BBh
23	17h	DAC_CLKDIG_DELAY	R/W	-	-	-	-	-	PLL_DIG_DELAY[2:0]			0000 0010	02h
31	1Fh	PAGE_ADDRESS	R/W	-	-	-	-	-	PAGE[2:0]			0000 0000	00h

[1] u = undefined at power-up or after reset.

10.18.5 Page 1 bit definition detailed description

The tables in this section contain detailed descriptions of the page 1 registers.

Table 36. MDS_MAIN register (address 00h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7 to 6	MDS_EQCHECK[1:0]	R/W		lock mode
			00	**lock when (early = 1 and late = 1)**
			01	lock when (early = 1, late = 1 and equal = 1)
			10	lock when equal = 1
			11	force lock (equal-check = 1)
5	MDS_RUN	R/W		evaluation process restart control
			0	**no action**
			1	(0 ≥ 1) transition restarts evaluation_counter
4	MDS_NCO	R/W		NCO synchronization
			0	**no action**
			1	enable
3	MDS_NCO_PULSE	R/W		NCO pulse
			0	**no action**
			1	manual control NCO tuning
2	MDS_SREF_DIS	R/W		internal pulse generation
			0	normal mode
			1	**disable**
1	MDS_MASTER	R/W		MDS mode selection
			0	**slave mode**
			1	master mode
0	MDS_ENA	R/W		MDS function control
			0	**disable**
			1	enable

Table 37. MDS window time registers (address 01h to 02h) bit description

*Legend: * reset value; <= mandatory value*

Address	Register	Bit	Symbol	Access	Value	Description
01h	MDS_WIN_PERIOD_A	7 to 0	MDS_WIN_ PERIOD_A[7:0]	R/W	-	determines MDS window LOW time
02h	MDS_WIN_PERIOD_B	7 to 0	MDS_WIN_ PERIOD_B[7:0]	R/W	-	determines MDS window HIGH time

Table 38. MDS_MISCCNTRL0 register (address 03h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
4	MDS_EVAL_ENA	R/W		MDS evaluation
			0	disable
			1	**enable**

Table 38. MDS_MISCCNTRL0 register (address 03h) bit description *...continued*

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
3	MDS_PRERUN_ENA	R/W		automatic MDS start-up
			0	**no mds_win/mds_ref generation in advance**
			1	mds_win/mds_ref run-in before mds_evaluation
2 to 0	MDS_PULSEWIDTH[2:0]	R/W		width of MDS (in output clock -periods)
			000	**1 DAC clock period**
			001	2 DAC clock periods
			010 to 111	(mds_pulsewidth − 1) × 4 DAC clock periods

Table 39. MDS_MAN_ADJUSTDLY register (address 04h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	MDS_MAN	R/W		adjustment delays mode
			0	**auto-control adjustment delays**
			1	manual control adjustment delays
6 to 0	MDS_MAN_ADJUSTDLY[6:0]	R/W		adjustment delay value
			-	if MDS_MAN = 0 then initial value adjustment delay
			-	if MDS_MAN = 1 then controls adjustment delay

Table 40. MDS_AUTO_CYCLES register (address 05h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7 to 0	MDS_AUTO_CYCLES[7:0]	R/W	-	number of evaluation cycles applied for MDS. If set to 255 then IC continuously generates/monitors the MDS pulse

Table 41. MDS_MISCCNTRL1 register (address 06h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	MDS_SR_CKEN	R/W	-	lock mode
			0	**free-running MDS_SR_CKEN**
			1	MDS_SR_CKEN forced low
6	MDS_SR_LOCKOUT	R/W		lockout detector soft reset
			0	**MDS_SR_LOCKOUT in use**
			1	MDS_SR_LOCKOUT forced low
5	MDS_SR_LOCK	R/W		lock detector soft reset
			0	**MDS_SR_LOCK in use**
			1	MDS_SR_LOCK forced low
4	MDS_RELOCK	R/W		relock mode
			0	**no action**
			1	relock when lockout occurs
3 to 0	MDS_LOCK_DELAY[3:0]	R/W	-	number of succeeding 'equal' detections until lock

Table 42. MDS_OFFSET_DLY register (address 07h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
4 to 0	MDS_OFFSET_DLY[6:0]	R/W	-	delay offset for dataflow (two's complement [−16 to 15]

Table 43. MDS_ADJDELAY register (address 08h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
6 to 0	MDS_ADJDELAY[6:0]	R	-	actual value adjustment delay

Table 44. MDS status registers (address 09h to 0Ah) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
09h	MDS_STATUS0	7	EARLY	R		early signal (sampled) from early-to-late detector
					0	false
					1	true
		6	LATE	R		late signal (sampled) from early-to-late detector
					0	false
					1	true
		5	EQUAL	R		equal signal (sampled) from early-to-late detector
					0	false
					1	true
		4	MDS_LOCK	R		result equal-check
					0	false
					1	true
		3	EARLY_ERROR	R		adjustment delay maximum value stops the search
					0	false
					1	true
		2	LATE_ERROR	R		adjustment delay minimum value stops the search
					0	false
					1	true
		1	EQUAL_FOUND	R		evaluation logic has detected equal condition
					0	false
					1	true
		0	MDS_ACTIVE	R		evaluation logic active
					0	false
					1	true

Table 44. MDS status registers (address 09h to 0Ah) bit description *...continued*

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
0Ah	MDS_STATUS1	5	ADD_ERR	R		adjustment delay error detection
					0	OK
					1	delay offset cannot be applied in available range
		4 to 3	MDS_EN_PHASE[1:0]	R		MDS enable phase
					00	enable phase = 0
					01	enable phase = 1 (only for ×2)
					10	enable phase = 2 (only for ×2 and ×4)
					11	enable phase = 3 (only for ×2)
		2	MDS_PRERUN	R		MDS-PRERUN phase active flag
					0	false
					1	true
		1	MDS_LOCKOUT	R		MDS_LOCKOUT detected flag
					0	false
					1	true
		0	MDS_LOCK	R		MDS_LOCK flag
					0	false
					1	true

Table 45. Bias current control registers (address 0Eh to 15h) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
0Eh	DAC_CURRENT_AUX	3 to 0	DAC_AUX_BIAS[3:0]	R/W	-	bias current control (see Table 46)
0Fh	DAC_CURRENT_0	3 to 0	DAC_DIG_BIAS[3:0]	R/W	-	
10h	DAC_CURRENT_1	3 to 0	DAC_MST_BIAS[3:0]	R/W	-	
11h	DAC_CURRENT_2	3 to 0	DAC_DRV_BIAS[3:0]	R/W	-	
12h	DAC_CURRENT_3	3 to 0	DAC_SLV_BIAS[3:0]	R/W	-	
13h	DAC_CURRENT_4	3 to 0	DAC_CK_BIAS[3:0]	R/W	-	
14h	DAC_CURRENT_5	3 to 0	DAC_CAS_BIAS[3:0]	R/W	-	
15h	DAC_CURRENT_6	3 to 0	DAC_BLD_BIAS[3:0]	R/W	-	

Table 46. Bias current control table

BIAS[3:0]	Deviation from nominal current
0 0 0	−30 %
0 0 1	−20 %
0 1 0	−10 %
0 1 1	0 %
1 0 0	+10 %

Table 46. Bias current control table *…continued*

BIAS[3:0]	Deviation from nominal current
1 0 1	+20 %
1 1 0	+30 %
1 1 1	+40 %

Table 47. DAC_PON_SLEEP register (address 16h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	DAC_B_PON	R/W	-	DAC B power control
			0	power-down
			1	**power on**
6	DAC_B_SLEEP	R		DAC B mode selection
			0	**normal operation**
			1	Sleep mode
5	DAC_B_COM_PD	R		commutator B control
			0	disable (power-down)
			1	**enable**
4	DAC_B_BLEED_PD	R		DAC B bleed current control
			0	disable (power-down)
			1	**enable**
3	DAC_A_PON	R		DAC A power control
			0	power-down
			1	**power on**
2	DAC_A_SLEEP	R		DAC B mode selection
			0	**normal operation**
			1	Sleep mode
1	DAC_A_COM_PD	R		commutator A control
			0	disable (power-down)
			1	**enable**
0	DAC_A_BLEED_PD	R		DAC A bleed current control
			0	disable (power-down)
			1	**enable**

Table 48. DAC_TEST_8 register (address 17h) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
2 to 0	PLL_DIG_DELAY[2:0]	R/W	-	digital clock delay offset of PLL/CKGEN_DIV8

Table 49. SPI_PAGE register (address 1Fh) bit description

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
2 to 0	PAGE[2:0]	R/W	-	SPI page address

10.18.6 Page A register allocation map

Table 50 shows an overview of all registers on page A (0Ah in hexadecimal).

Table 50. Page_0A register allocation map

Address		Register name	R/W	Bit definition								Default	
				Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Bin	Hex
0	00h	MAIN_CNTRL	R/W	-	-	-	LD_PD	PD_CNTRL	CAL_ CNTRL	RST_ DCKL	RST_ LCKL	0000 0011	03h
1	01h	MAN_LDCLKDEL	R/W	-	-	-	-	LDCLK_DEL[3:0]				0000 0000	00h
2	02h	DBG_LVDS	R/W	-	-	-	-	SBER	RESERVED			0000 0000	00h
4	04h	RST_EXT_LDCLK	R/W	RST_EXT_LCLK_TIME[7:0]								0011 1111	3Fh
5	05h	RST_EXT_DCLK	R/W	RST_EXT_DCLK_TIME[7:0]								0010 0000	20h
6	06h	DCMSU_PREDIV	R/W	DCMSU_PREDIVIDER[7:0]								0001 1110	1Eh
8	08h	LD_POL_LSB	R/W	LD_POL[7:0]								0000 0000	00h
9	09h	LD_POL_MSB	R/W	LD_POL[15:8]								0000 0000	00h
10	0Ah	LD_CNTRL	R/W	PARITYC	DESCRAMBLE	SEL_EN[1:0]		WORD_SWAP	LDAB_ SWAP	IQ_ FORMAT	EDGE_ LDCLK	0000 0011	03h
11	0Bh	MISC_CNTRL	R/W	SR_CDI	RESERVED	I_LEV_ CNTRL[1:0]		Q_LEV_CNTRL[1:0]		CDI_MODE[1:0]		0000 0000	00h
12	0Ch	I_DC_LVL_LSB	R/W	I_DC_LEVEL[7:0]								0000 0000	00h
13	0Dh	I_DC_LVL_MSB	R/W	I_DC_LEVEL[15:8]								0100 0000	20h
14	0Eh	Q_DC_LVL_LSB	R/W	Q_DC_LEVEL[7:0]								0000 0000	00h
15	0Fh	Q_DC_LVL_MSB	R/W	Q_DC_LEVEL[15:8]								0100 0000	20h
27	1Bh	TYPE_ID	R	DAC	FRONTEND[1:0]		DUAL	DSP[1:0]		BIT_RES[1:0]		0011 1010	3Ch

Table 50. Page_0A register allocation map *...continued*

Address		Register name	R/W	Bit definition								Default	
				Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Bin	Hex
28	1Ch	DAC_VERSION	R	DAC_VERSION_ID[7:0]								0000 0001	01h
29	1Dh	DIG_VERSION	R	DIG_VERSION_ID[7:0]								0000 0001	01h
30	1Eh	LD_VERSION	R	LVDS_VERSION_ID[7:0]								0000 0001	01h
31	1Fh	PAGE_ADDRESS	R/W	-	-	-	-	-	PAGE[2:0]			0000 0000	00h

10.18.7 Page A bit definition detailed description

The tables in this section contain detailed descriptions of the page A registers.

Table 51. Register MAIN_CNTRL (address 00h)
Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
4	LD_PD	R/W		LVDS interface power-down (control possible only when PD_CNTRL = 1)
			0	**switched on**
			1	switched off
3	PD_CNTRL	R/W		power-down modes controlled by
			0	**DCMSU block**
			1	SPI registers
2	CAL_CNTRL	R/W		compensation delay controlled by
			0	**DCMSU block (automatic calibration)**
			1	SPI registers (manual control)
1	RST_DCLK	R/W		reset DCLK
			0	disable
			1	**enable**
0	RST_LCLK	R/W		reset LVDS clock
			0	disable
			1	**enable**

Table 52. Register MAN_LDCLKDEL (address 01h)
Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
3 to 0	LDCLK_DEL[3:0]	R/W		LVDS clock compensation delay (control only if CAL_CNTRL = 1)
			-	4-bit compensation delay for LVDS clock

Table 53. Register DBG_LVDS (address 02h)
Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
3	SBER	R/W		simple BER control
			0	**no action**
			1	simple BER active
2 to 0	RESERVED	R/W	**000**	**reserved**

Table 54. Extension time reset registers (address 04h to 05h) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
04h	RST_EXT_LCLK	7 to 0	RST_EXT_LCLK_ TIME[7:0]	R/W		specifies extension time reset, expressed in LVDS clock periods
					-	8 bits for the extension time reset
05h	RST_EXT_DCLK	7 to 0	RST_EXT_DCLK_ TIME[7:0]	R/W		specify extension time reset, expressed in DCLK periods
					-	8 bits for the extension time reset

Table 55. Register DCSMU_PREDIV (address 06h)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7 to 0	DCMSU_PREDIVIDER[7:0]	R/W		predivider value for the DCMSU, expressed in LVDS clock period
			-	8 bits for the predivider value

Table 56. LSB/MSB of polarity registers (address 08h to 09h) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
08h	LD_POL_LSB	7 to 0	LD_POL[7:0]	R/W		toggles polarity of corresponding bit pair within LD[7:0]
					-	most significant 6 bits for the polarity toggle
09h	LD_POL_MSB	7 to 0	LD_POL[15:8]		-	most significant 6 bits for the polarity toggle

Table 57. Register LD_CNTRL (address 0Ah)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	PARITYC	R/W		parity check
			0	disable
			1	enable
6	DESCRAMBLE	R/W		Descramble control
			0	**disable descrambling**
			1	enable descrambling
5 to 4	SEL_EN[1:0]	R/W		LDVS data enable
			00	**LDVS data enable = align signal from channel A**
			01	LDVS data enable = align signal from channel B
			10	LDVS data enable = 0
			11	LDVS data enable = 1
3	WORD_SWAP	R/W		reverse order for LVDS path
			0	**normal operation**
			1	MSB to LSB order reversed

Table 57. Register LD_CNTRL (address 0Ah) *…continued*

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
2	LDAB_SWAP	R/W		swaps LVDS A and LVDS B paths
			0	**normal operation**
			1	LVDS A and LVDS B paths are swapped
1	IQ_FORMAT	R/W		specify IQ supplied format
			0	folded
			1	**interleaved**
0	EDGE_LDCLK	R/W		specify sampling edge for LVDS data path
			0	falling edge of LDCLK
			1	**rising edge of LDCLK**

Table 58. Register MISC_CNTRL (address 0Bh)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	SR_CDI	R/W		CDI block software reset control
			0	**no action**
			1	perform a software reset on CDI
6	RESERVED	R/W	0	reserved
5 to 4	I_LEV_CNTRL[1:0]	R/W		specifies output from CDI for I path
			00	**normal operation (CDI data output sent to digital signal processing input)**
			01	if LDVS data enable = 1, then normal operation; if LDVS data enable = 0, then digital signal processing input = I_DC_LEVEL register value
			10	digital signal processing input = I_DC_LEVEL
			11	digital signal processing input = I_DC_LEVEL
3 to 2	Q_LEV_CNTRL[1:0]	R/W		specifies output from CDI for Q path
			00	**normal operation (CDI data output sent to digital signal processing input)**
			01	if LDVS data enable = 1, then normal operation; if LDVS data enable = 0, then digital signal processing input = Q_DC_LEVEL register value
			10	digital signal processing input = Q_DC_LEVEL
			11	digital signal processing input = Q_DC_LEVEL
1 to 0	CDI_MODE[1:0]	R/W		specifies CDI mode
			00	**cdi_mode 0 (×2 mode)**
			01	cdi_mode 1 (×4 mode)
			10	cdi_mode 2 (×8 mode)
			11	not used

Table 59. LDS/MDS of I/Q DC levels registers (address 0Ch to 0Fh) bit description

Default values are shown highlighted.

Address	Register	Bit	Symbol	Access	Value	Description
0Ch	I_DC_LVL_LSB	7 to 0	I_DC_LEVEL[7:0]	R/W		I_DC_LEVEL
					-	least significant 8 bits for I_DC_LEVEL
0Dh	I_DC_LVL_MSB	7 to 0	I_DC_LEVEL[15:8]		-	most significant 8 bits for I_DC_LEVEL
0Eh	Q_DC_LVL_LSB	7 to 0	Q_DC_LEVEL[7:0]	R/W		Q_DC_LEVEL
					-	least significant 8 bits for Q_DC_LEVEL
0Fh	Q_DC_LVL_MSB	7 to 0	Q_DC_LEVEL[15:8]		-	most significant 8 bits for Q_DC_LEVEL

Table 60. Register TYPE_ID (address 1Bh)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7	DAC	R		calibration
			0	uncalibrated device
			1	**calibrated device**
6 to 5	FRONTEND	R	**01**	**LVDS input interface**
4	DUAL	R	0	dual DAC
3 to 2	DSP	R		internal digital signal processing
			11	interpolation filter + SSBM
			10	SSBM
			01	interpolation filter
			00	none
1 to 0	BIT_RES	R		DAC bit resolution
			00	**16 bits**
			01	14 bits
			10	12 bits
			11	10 bits

Table 61. Register DAC_VERSION (address 1Ch)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7 to 0	DAC_VERSION_ID[7:0]	R/W		DAC version number
			-	8 bits for the DAC version number

Table 62. Register DIG_VERSION (address 1Dh)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7 to 0	DIG_VERSION_ID[7:0]	R/W		digital version number
			-	8 bits for the digital version number

Table 63. Register LVDS_VERSION (address 1Eh)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
7 to 0	LVDS_VERSION_ID[7:0]	R/W		LVDS receiver version number
			-	8 bits for the LVDS receiver version number

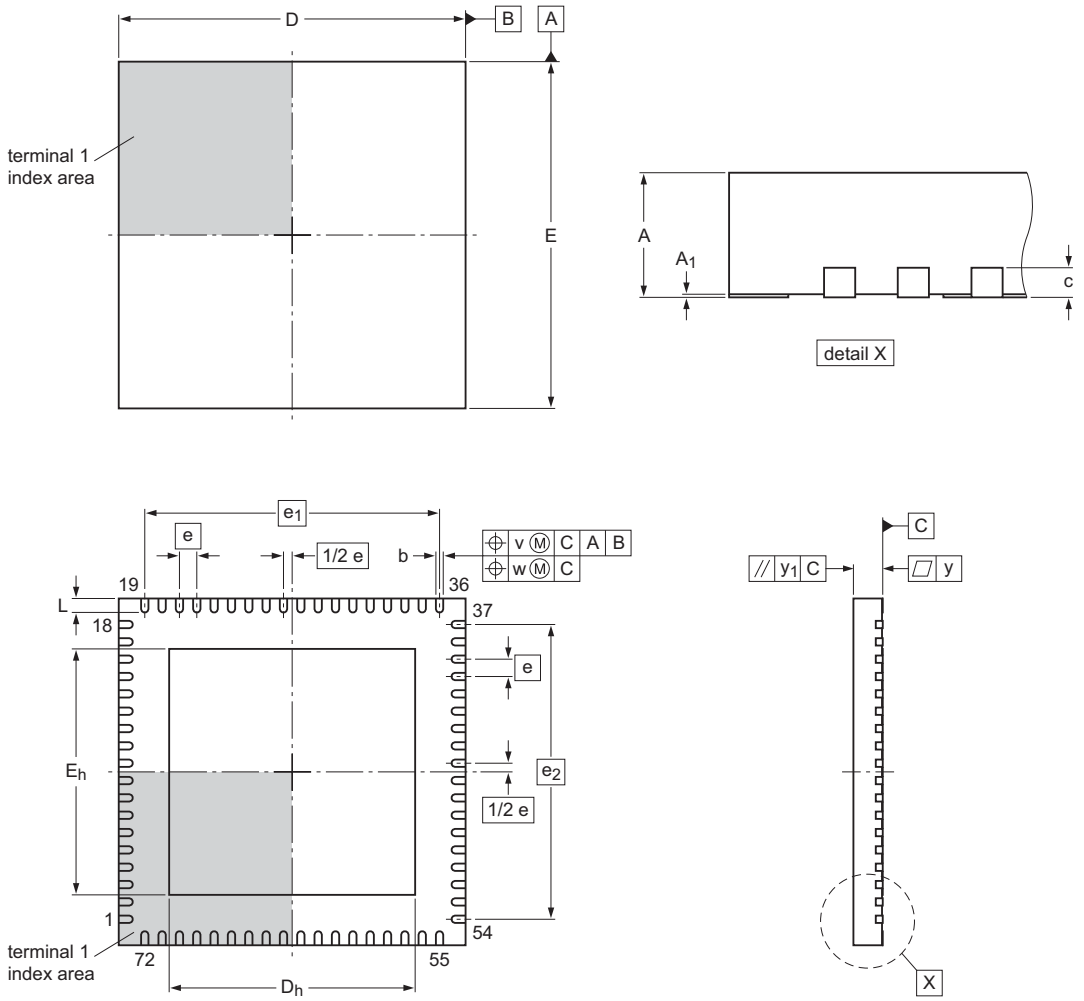
Table 64. Register PAGE_ADD (address 1Fh)

Default values are shown highlighted.

Bit	Symbol	Access	Value	Description
2 to 0	PAGE[2:0]	R/W		Page address
			-	current page address

11. Package outline

HVQFN72: plastic thermal enhanced very thin quad flat package; no leads; 72 terminals; body 10 x 10 x 0.85 mm **SOT813-3**



Dimensions

Unit		A	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	e_2	L	v	w	y	y_1
	max	1.00	0.05	0.30		10.1	7.2	10.1	7.2				0.5				
mm	nom	0.85	0.02	0.21	0.2	10.0	7.1	10.0	7.1	0.5	8.5	8.5	0.4	0.1	0.05	0.05	0.1
	min	0.80	0.00	0.18		9.9	7.0	9.9	7.0				0.3				

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot813-3_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT813-3	- - -	- - -	- - -			~~10-04-02~~ 11-06-20

Fig 30. Package outline SOT813-3 (HVQFN72)

12. Abbreviations

Table 65. Abbreviations

Acronym	Description
BW	BandWidth
BWA	Broadband Wireless Access
CDI	Clock Domain Interface
CDMA	Code Division Multiple Access
CML	Current Mode Logic
CMOS	Complementary Metal Oxide Semiconductor
DAC	Digital-to-Analog Converter
EDGE	Enhanced Data rates for GSM Evolution
FIR	Finite Impulse Response
GSM	Global System for Mobile communications
IF	Intermediate Frequency
IMD3	Third Order InterModulation
LMDS	Local Multipoint Distribution Service
LO	Local Oscillator
LVDS	Low-Voltage Differential Signaling
NCO	Numerically Controlled Oscillator
NMOS	Negative Metal-Oxide Semiconductor
PLL	Phase-Locked Loop
SFDR	Spurious-Free Dynamic Range
SPI	Serial Peripheral Interface
WCDMA	Wide band Code Division Multiple Access
WLL	Wireless Local Loop

13. Glossary

13.1 Static parameters

INL — The deviation of the transfer function from a best fit straight line (linear regression computation).

DNL — The difference between the ideal and the measured output value between successive DAC codes.

13.2 Dynamic parameters

Spurious-Free Dynamic Range (SFDR) — The ratio between the RMS value of the reconstructed output sine wave and the RMS value of the largest spurious observed (harmonic and non-harmonic, excluding DC component) in the frequency domain.

Decibels relative to full scale (dBFS) — Unit used in a digital system to measure the amplitude level in decibel relative to the maximum peak value.

InterModulation Distortion (IMD) — From a dual-tone digital input sine wave (these two frequencies being close together), the intermodulation distortion products IMD2 and IMD3 (second order and third order components) are defined below.

IMD2 — The ratio between the RMS value of either tone and the RMS value of the worst second order Intermodulation product.

IMD3 — The ratio between the RMS value of either tone and the RMS value of the worst third order Intermodulation product.

Total Harmonic Distortion (THD) — The ratio between the RMS value of the harmonics of the output frequency and the RMS value of the output sine wave. Usually, the calculation of THD is done on the first 5 harmonics.

Signal-to-Noise Ratio (SNR) — The ratio between the RMS value of the reconstructed output sine wave and the RMS value of the noise excluding the harmonics and the DC component.

Restricted BandWidth Spurious-Free Dynamic Range ($SFDR_{RBW}$) — The ratio between the RMS value of the reconstructed output sine wave and the RMS value of the noise, including the harmonics, in a given bandwidth centered around f_{offset}.

14. Revision history

Table 66. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
DAC1617D1G0 v.1.1	20110930	Objective data sheet	-	DAC1617D1G0 v.1
Modifications:	• Input resistance in section Clock inputs (pins CLKP, CLKN) of Table 5 “Characteristics” has been updated.			
DAC1617D1G0 v.1	20110906	Objective data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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17. Tables

18. Contents

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